

PowerEdge Servers

Accelerate Transformation Anywhere



The Next Generation PowerEdge Server Portfolio

Purpose-built to address evolving customer needs

AI / ML



XE9640



XE9680



XE8640

Edge



XR5610



XR8000



XR7620



XR4000

CSP



HS5620



HS5610

Core



R760



R7625



R6625



R760xs



R760xd2



R860



R760xa



R7615



C6620



MX760



R960



R660



R6615



R660xs



T560

Accelerate AI Outcomes



PowerEdge XE9680



PowerEdge XE9640



PowerEdge XE8640



POWERED BY 4TH GENERATION INTEL XEON SCALABLE PROCESSORS

No-compromise Accelerated AI

- 8x NVIDIA H100 SXM5 700W 80GB NVLink GPUs or
- 8x NVIDIA A100 SXM4 500W 80GB NVLink GPUs
- Full NVLINK interconnectivity
- Air cooled operation (up to 35C)

Dense Acceleration

- 4x Intel Data Center Max Series GPU with GPU-GPU connectivity
- Dell Smart Cooled DLC GPUs
- 1:1 GPU-I/O enables faster data operations

Superior Performance

- 4x NVIDIA H100 SXM5 700W 80GB NVLink GPUs
- Full NVLINK interconnectivity
- GPU Direct Storage for fast data intake

Accelerate at the Edge



Powerful inside and out

- 1-socket, 2-socket, and multi-node available
- -5C to 55C operating temps
- GPU support



Expanded portfolio

- Compatible with Dell Edge /Telco Solutions
- New multi-node design XR4000 & XR8000



Energy flexibility

- 110-240V AC power
- -48V DC power
- Redundant PSUs

Expand your compute outside the datacenter

XR7620



2S/2U

XR5610



1S/1U

XR4000



Multi-Node
Xeon D

XR8000



Multi-Node
Xeon SP

Accelerate at Scale



Purpose-built for CSPs

- Rapidly scale SaaS, PaaS, and IaaS infrastructures
- Technology optimization without the financial and operational burden of supporting extreme configurations
- Speed time to market with early access to units for workload validation



Expanded portfolio

Available exclusively through the Hyperscale Next program



HS5610



HS5620



Optimized for open ecosystem

- Dell Open Server Manager built on OpenBMC™
- Designed, tested, and validated on select Dell PowerEdge cloud scale servers
- Save time with a selection of validated vendor firmware COMMs cards and SSDs

Scale your architecture at your pace with Purpose-built solutions

Core



PowerEdge R760



PowerEdge R660



PowerEdge R760xa

POWERED BY 4TH GENERATION INTEL XEON SCALABLE PROCESSORS



PowerEdge R960



PowerEdge R860

Core Scale Out



PowerEdge R760xs



PowerEdge R660xs



PowerEdge C6620

POWERED BY 4TH GENERATION INTEL XEON SCALABLE PROCESSORS

Thoughtfully crafted

- To fit your current infrastructure and deliver the right performance to support demanding enterprise applications

Easily configured

- Includes a variety of components that are interchangeable to suit your needs

A breeze to cool

- Equipped with patented Multi-Vector air cooling saving on liquid cooling options

The Next Generation PowerEdge Server Portfolio

Purpose-built to address evolving customer needs

Core

Acceleration-Optimized



XE9680



XE9640



XE8640



R760xa

Modular



MX760



C6620



R760xd2



R7615



R6615

Mainstream



R760



R660



R7625



R6625

Mainstream 4 Socket



R960



R860



T560

Mainstream Optimized



R760xs



R660xs

Edge



XR8000



XR5610



XR7620



XR4000

Scale

Cloud Service Providers



HS5620



HS5610



.Next PowerEdge

Reimagine IT Possibilities...

What's new with our R660/R760 portfolio?



Workloads

Data center standardization

High density virtualization

Online transaction processing

Database analytics

Virtual desktop infrastructure

In-memory database



R660 : 1U/2S

Denser 2 socket



R760: 2U/2S

Maximum configuration flexibility

Provides performance and versatility as needed to address your most demanding applications



Max Performance

Extract value faster from collected data with high-performance processors, GPUs, next-generation storage for demanding workloads like AI/ML



Air cooled at peak performance

Take advantage of configurations with high performance CPUs in an air-cooled chassis



Gain agility

Can be deployed for maximum scalability in vSAN (HCI) environments or for maximum application performance in bare metal environments with the new PERC12

PowerEdge R660

Support for up to 16 Drives

- Storage options for SAS4/SATA/ NVMe Gen4 and Gen5
- Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
- Next-gen hardware NVMe RAID

Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- Up to 4800 MT/s (1DPC) or 4400 MT/s (2DPC)



2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor
- High-bandwidth memory CPUs

Support for GPU

- 3 x SW GPUs

Flexible I/O

- Up to 3 x PCIe Slots
- Optional 2 x 1GbE LOM + 1 x OCP 3.0 slot

- Smart Cooling
- Direct Liquid Cooling
- Designed for growing scale-out solutions and air-cooled support
- Industry-leading manageability and security

TARGET WORKLOADS



High Performance Simulation & Modeling

Deliver unparalleled performance in air-cooled 1U HPC clusters with high-bandwidth memory CPU that feature high CPU core count combined with 4x more memory bandwidth than regular DDR5 DIMMs.



Online Transaction Processing

Enable faster, more secure online transactions with next-gen high performance Intel CPUs built with Gen5 PCIe NVMe drives and high-capacity memory.



All-Flash vSAN

Advance HCI implementations and gain higher throughput by deploying vSAN nodes equipped with high-frequency CPUs on NVMe direct-attached storage configurations.

MAINSTREAM

Technical Specifications – R640, R650 & R660

Features	PowerEdge R640	PowerEdge R650	PowerEdge R660
CPU	Up to two 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor Support for up to 2 x 205W proc	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 40 cores per processor Support for up to 2 x 270W processors Direct Liquid Cooling support	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors Direct Liquid Cooling support
Memory	Up to 24 x DDR4 RDIMM, LRDIMM, Optane Persistent Memory 100 (Apache Pass): Yes NVDIMM: Yes DIMM Speed: Up to 2933 MT/s	Up to 32 x DDR4 RDIMMs/LRDIMMs (8TB + Optane Persistent Memory 200 Series) Optane Persistent Memory 200 Series (Barlow Pass): Yes DIMM Speed: Up to 3200 MT/s corrected	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 4 x 3.5" SAS/SATA HDDs Up to 10 x 2.5" SAS/SATA HDD/SSDs or NVMe SSDs Up to 2 x 2.5" (rear) SAS/SATA HDD/SSDs or NVMe SSDs Internal: iDSDM and BOSS (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS, SATA 6Gb	Up to 4 x 3.5" SAS/SATA HDDs Up to 10 x 2.5" SAS/SATA HDD/SSDs; or NVMe SSDs Up to 2 x 2.5" (rear) SAS/SATA HDD/SSDs; or NVMe SSDs Rear BOSS-S2 (2 x M.2 SATA) for boot Internal: iDSDM or USB Bandwidth: 12Gb/6Gb SAS, SATA 6Gb	Up to 10 x 2.5" SAS/SATA HDD/SSDs; or NVMe SSDs Up to 2 x 2.5" (rear) SAS/SATA HDD/SSDs; or NVMe SSDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot Internal: iDSDM or USB Bandwidth: Up to 32Gb NVMe/24Gb SAS/6Gb SATA
Storage Controller	HW RAID: PERC 9 & PERC 10 (dual PERC option) Chipset SATA/SW RAID: Yes	HW RAID: PERC 10.5 & 11 (dual PERC option) HW NVMe RAID Chipset SATA/SW RAID: Yes	HW RAID: PERC 11 & 12 (dual PERC option) HW SAS4/SATA/NVMe RAID SW RAID: Yes
Network	1 NDC 4 x 1GbE, 4 x 10GbE, 2 x 10GbE + 2 x 1GbE, or 2 x 25GbE	2 x 1GbE LOM + 1 x OCP 3.0	Optional 2 x 1GbE LOM, 1 x OCP 3.0
PCIe Slots	Up to 3 x PCIe Slots Gen3	Up to 3 x PCIe Slots Gen4, SNAP I/O option	Up to 3 x PCIe Slots (Gen4 / Gen5), SNAP I/O option
GPU	3 x SW GPUs	3 x SW GPUs	3 x SW GPUs
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB port, 1 x USB 3.0 (optional) + 1 x VGA Rear: 1 x Dedicated iDRAC Ethernet port, 1 x Serial, 2 x USB 3.0, 1 x VGA Internal USB	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB port, 1 x VGA Rear: 1 x Dedicated iDRAC Ethernet port, 1 x Serial (optional), 1 x USB 3.0, 1 x USB 2.0, 1 x VGA (optional for Liquid Cooling configurations) Internal USB	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB port, 1 x VGA Rear: 1 x Dedicated iDRAC Ethernet port, 1 x Serial (optional), 1 x USB 2.0, 1 x USB 3.0, 1 x VGA (optional for Liquid Cooling configurations) Internal: USB (optional)
System Management	iDRAC9, iDRAC Direct, iDRAC RESTful with Redfish, Quick Sync 2 wireless module (optional), OpenManage Enterprise and Power Manager, OpenManage Mobile	iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, Quick Sync 2 wireless module, OpenManage Enterprise and Power Manager, OpenManage Mobile	iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, Quick Sync 2 wireless module, OpenManage Enterprise and Plugins (Power Manager, SupportAssist, Update Manager) , OpenManage Mobile
High Availability	Hot Plug/RAID controlled drives, PSU, Hot-plug fans.	Hot Plug/RAID controlled drives, PSU, Hot-plug fans. Hot-plug BOSS	Hot Plug/RAID controlled drives, PSU, Hot-plug fans. Hot-plug BOSS
Power Supplies	AC (Platinum): 495W, 750W, 1100W, 1600W, AC (Titanium): 750W LVDC @-48VDC Input: 1100W	AC (Platinum): 800W, 1400W AC (Titanium): 1100W LVDC @-48V -60V DC Input: 1100W	AC (Platinum): 800W, 1400W AC (Titanium): 700W, 1100W, 1800W LVDC @-48VDC Input: 1100W
Dimension	H x W x D: 42.8mm x 482mm x 809mm	H x W x D: 42.8mm x 482mm x 809mm	H x W x D: 42.8mm x 482mm x 809mm
Form Factor	1U Rack Server	1U Rack Server	1U Rack Server

Reimagine IT Possibilities...

What's new with our **AMD 2 socket** portfolio?



Workloads

High performance compute (HPC)

Virtualization

Virtual desktop integration (VDI)

Data analytics



R6625 : 1U/2S

Most dense 2S offer



R7625: 2U/2S

Maximized PCIe & Storage

Extremely powerful, dense, and air or liquid cooled,
to be the backbone of your data center.



Extreme Performance

With two AMD EPYC 4th gen enables DDR5 memory, PCIe Gen 5 all in an air-cooled and smaller footprint.



More virtual machine density

Packed with 50% more CPU cores and supports up to 6 GPUs for VDI consolidation.



Increased expandability

Store more data per server with 33% more E3.S drives and save precious data center floor space.

PowerEdge R7625

A step ahead in processing

- Powered by up to two 4th Generation AMD EPYC™ processors with up to 96 cores per processor
- Up to 24 x DDR5 RDIMMs (6TB max)

I/O and connectivity

- Up to 8 x PCIe slots (up to 4 x Gen5)
- OCP 3.0 for network cards



Flexible storage

- Up to 12 x 3.5" – 12Gb SAS, 6Gb SATA
- Up to 24 x 2.5" – 12Gb SAS, 6Gb SATA, NVMe
- Up to 32 x E3.S – NVMe
- Rear: Up to 4 x 2.5" Hot Plug SAS/SATA or NVMe HDDs, Up to 4 x E3.S NVMe

- Smart Cooling
- Direct Liquid Cooling (DLC) Support
- Industry-leading manageability and security

TARGET WORKLOADS



Data Analytics

Maximized storage and memory configuration option enables HPC, ML/DL/AI and rendering



All Flash SDS

24 2.5" U.2 Gen4 NVMe or 32 E3.S drives supports all flash storage



VDI

Balanced core count and GPU to support for maximum numbers of end users

MAINSTREAM

Technical Specifications – R7525, R7625

Features	PowerEdge R7525	PowerEdge 7625
CPU	Up to two 2 nd or 3 rd Generation AMD EPYC™ processors with up to 64 cores per processor Up to 280W (cTDP)	Up to two 4 th Generation AMD EPYC™ processors with up to 96 cores per processor Target up to 400W (cTDP)
Memory	DDR4: Up to 32 x DDR4 RDIMM, LRDIMM (4TB) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 24 x DDR5 RDIMMs (6TB) DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 12 x 3.5" – 12Gb SAS, 6Gb SATA Up to 24 x 2.5" – 12Gb SAS, 6Gb SATA Rear: Up to 2 x 2.5" Hot Plug SAS/SATA or NVMe HDDs Internal: 2 x M.2 (BOSS)	Up to 24 x 2.5" SAS/SATA HDD/SSDs, or NVMe Up to 12 x 3.5" SAS/SATA HDD/SSDs Up to 32 E3.S NVMe Rear: Up to 4 x 2.5" Hot Plug SAS/SATA or NVMe HDDs, Up to 4 x E3.S NVMe Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot Bandwidth: 12Gb/6Gb SAS
PCIe Storage	Up to 24 NVMe Direct	Up to 32 E3.S NVMe Direct (G5 x 2 PCIe Lanes)
Storage Controller	HW RAID: PERC 10.5, PERC 11 HW NVMe RAID: PERC11 Chipset SATA/SW RAID: Yes	HW RAID: PERC11, PERC12 HW NVMe RAID: PERC11, PERC12 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM + 1 x OCP 3.0	LOM Riser + 1 x OCP 3.0
PCIe slots	Up to 8 x PCIe x16 Gen4 slots @ 16GT/s	Up to 8 x PCIe x16 slots, 4 x PCIe Gen5, 4 x PCIe Gen4
GPU	Up to 3 DW GPU or up to 6 SW 75W GPU	Up to 2 500W DWFL (Target 700W) or up to 6 150W SWFL
Integrated Ports	Front: 1 port (USB 2.0), 1 (micro-USB, iDRAC Direct) Rear: 1 port (USB 3.0) + 1 port (USB 2.0) Internal: 1 port (USB 2.0)	Front: 1 port (USB 2.0), 1 (iDRAC Direct micro-USB) Rear: 1 port (USB 3.0) + 1 port (USB 2.0)
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	16G iDRAC Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS (2 x M.2)	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	800W, 1400W, 1100W	800W -48Vdc, 1100W, 1100W -48Vdc, 1400W, 1800W, 2400W, 2800W
Dimensions	2U x 700mm (27.6")	H x W x D: 2U x 434mm (17.08 in) x 736.29 mm (28.98 in)
Form Factor	2U Rack Server	2U Rack Server

Reimagine IT Possibilities...

What's new with our **AMD 2 socket** portfolio?



Workloads

High performance compute (HPC)

Virtualization

Virtual desktop integration (VDI)

Data analytics



R6625 : 1U/2S

Most dense 2S offer



R7625: 2U/2S

Maximized PCIe & Storage

Extremely powerful, dense, and air or liquid cooled,
to be the backbone of your data center.



Extreme Performance

With two AMD EPYC™ 4th gen enables DDR5 memory, PCIe Gen 5 all in an air-cooled and smaller footprint.



More virtual machine density

Packed with 50% more CPU cores and supports up to 6 GPUs for VDI consolidation.



Increased expandability

Store more data per server with 33% more E3.S drives and save precious data center floor space.

PowerEdge R6625

2 Socket Capable

- Powered by up to two 4th Generation AMD EPYC™ processors with up to 96 cores per processor
- Up to 24 x DDR5 RDIMMs (6TB max)

I/O and connectivity

- Up to 3 x PCIe slots (up to 2 x Gen5)
- OCP 3.0 for network cards



Flexible storage

- Up to 4 x 3.5" SAS/SATA or SSD
- Up to 10 x 2.5" SAS/SATA, SSD; or NVMe
- Up to 14 x E3.S Hot Plug NVMe
- HW NVMe RAID

- Smart Cooling
- Direct Liquid Cooling (DLC) Support
- Industry-leading manageability and security

TARGET WORKLOADS



HPC

HPC requiring 1DPC design for highest memory performance & scale out clusters.



Dense VDI

Multi GPU support to accelerate end user VDI performance



Virtualization

VMMark w/ vSAN World Record performance of 24.08 @ 28 tiles is 81.5% better than previous record

MAINSTREAM

Technical Specifications – R6525, R6625

Features	PowerEdge R6525	PowerEdge R6625
CPU	Up to two 2 nd or 3 rd Generation AMD EPYC™ processors with up to 64 cores per processor Up to 280W (cTDP)	Up to two 4 th Generation AMD EPYC™ processors with up to 96 cores per processor Target up to 400W (cTDP)
Memory	DDR4: Up to 32 x DDR4 RDIMM, LRDIMM (4TB) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 24 x DDR5 RDIMMs (6TB) DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 4 x 3.5" Hot Plug SAS/SATA HDDs Up to 12 x 2.5" (10 Front + 2 Rear) Hot Plug SAS/SATA/NVMe Up to 8 x 2.5" Hot Plug SAS/SATA HDD/SSDs Internal: Internal BOSS (2 x M.2)	Up to 4 x 3.5" Hot Plug SAS/SATA HDDs Up to 12 x 2.5" (10 Front + 2 Rear) Hot Plug SAS/SATA/NVMe Up to 14 x E3.S Hot Plug NVMe CPU Direct or 16 x E3.S Hot Plug NVMe with Dual Controllers Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot Bandwidth: 12Gb/6Gb SAS/SATA
PCIe Storage	Up to 12 (10+2) NVMe Direct	Up to: 12 x 2.5" (10 Front + 2 Rear) U.2 NVMe 14 x E3.S Hot Plug NVMe Direct 16 x E3.S Hot Plug NVMe with Dual Controllers
Storage Controller	HW RAID: PERC 10.5, PERC 11 HW NVMe RAID: PERC11 Chipset SATA/SW RAID: Yes	HW RAID: PERC11, PERC12 HW NVMe RAID: PERC11 PERC12 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM + 1 x OCP 3.0	LOM Riser + 1 x OCP 3.0
PCIe slots	Up to 3 x PCIe x16 Gen4 slots @ 16GT/s	Up to 3 x PCIe x16 slots, 2 x PCIe Gen5 , 1 x PCIe Gen4
GPU	Up to 3 Single-Wide GPU	Up to 3 75W LP or 2 150W FH/HL
Integrated Ports	Front: 1 port (USB 2.0), 1 (micro-USB, iDRAC Direct) Rear: 1 port (USB 3.0) + 1 port (USB 2.0) Internal: 1 port (USB 2.0)	Front: 1 port (USB 2.0), 1 (iDRAC Direct micro-USB) Rear: 1 port (USB 3.0) + 1 port (USB 2.0)
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	16G iDRAC Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
Power Supplies	800W, 1400W, 1100W	800W, 1100W, 1100W -48Vdc, 1400W, 1800W
High Availability	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS (2 x M.2)	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS-N1 (2 x M.2 NVMe) for boot
Dimensions	H x W x D: 1U x 700.7mm (21.6") or 751.5mm (29.6")	H x W x D: 1U x 434mm (17.08 in) x 736.27 mm (28.99 in)
Form Factor	1U Rack Server	1U Rack Server

Accelerate innovation...

What's new with our R860 & R960?



Workloads

Large In-Memory databases, SAP HANA

Virtualization, dense VDI and VM/Container operations

Mission & Business-critical operations across multiple segments including Financial, Healthcare



R860

4x CPUs and 64 DIMMs in 2U



R960

4x CPUs, 64 DIMMs, with additional storage and slots in 4U

Extreme acceleration for business, delivering business-critical and data-driven operational capabilities from core to hybrid cloud with scalable compute.



Accelerate your outcomes

Powerful performance for large in-memory database workloads, enabling faster business insights



Optimized for Dense Virtualization

Maximize VM and VDI operations with up to 240 CPU cores, by simplifying resource utilization and lowering TCO



Scalable flexibility

Scale up multiple workload needs, up to 16TB DDR5, up to 32 drives and 12 PCIe Gen5 slots

PowerEdge R860

Extreme Computing Power

- Up to four 4th Generation Intel® Xeon® Scalable processors with up to 60 cores per processor

Support for highest memory speed & capacity

- Up to 64 DDR5 RDIMMs
- Up to 4800 MT/s (1DPC) or 4400 MT/s (2DPC)



Support for up to 24 Drives

- Up to 24 NVMe direct attached drives
- Gen5 NVMe & SAS4 Support
- Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
- Next-gen hardware NVMe RAID

Flexible I/O

- Up to 8 x PCIe Gen 5 Slots
- 1 x OCP 3.0 slot
- Dedicated internal PERC

- Choice of 5 PSU (Gold or Platinum) to achieve sustainable energy goals
- Optimized for air-cooling in a variety of configurations, optional Dell Direct Liquid Cooling Support
- Industry-leading manageability and security

TARGET WORKLOADS



Large In-Memory Databases

With up to 64 DIMMs to maximize support for in-memory databases



Virtualization/VDI

With 4 CPUs and the greatest capacity for memory, storage, and I/O, this platform is optimal for the densest virtualization stacks



LOB Applications

Flexibility and capacity to support the most demanding Line Of Business applications

MAINSTREAM

Technical Specifications – R840, R860

Features	PowerEdge R840	PowerEdge R860
CPU	Up to four 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor Support for up to 4 x 205W processors	Up to four 4 th Generation Intel® Xeon® Scalable processors with up to 60 cores per processor. Support for up to 4 x 350W processors
Memory	DDR4: 48x DDR4 RDIMM/LRDIMM Optane Memory (Apache Pass): Yes NVDIMM: Yes	Up to 64 x DDR5 RDIMMs NVDIMM: No DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 24 x 2.5" SAS/SATA HDD/SSDs; or NVMe (Gen3) Up to 2 x 2.5" (rear) SAS/SATA HDD/SSDs; Internal: IDSDM and BOSS (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS	Up to 24 x 2.5" SAS/SATA HDD/SSDs Up to 24 x 2.5" NVMe SSDs Up to 8 E3.S NVMe Rear: Up to 2 x 2.5" Hot Plug SAS/SATA or NVMe HDDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot. No IDSM. Bandwidth: Up to 32Gb NVMe/24Gb SAS/6Gb SATA
Storage Controller	HW RAID: PERC 9 / PERC 10; Dual PERC option Chipset SATA/SW RAID: Yes	RAID (PERC 11 & 12) SAS / SATA / NVMe / RAID (PERC 11 & 12) SAS3 and SAS4 Chipset SATA/SW RAID: Yes
Network	1 x NDC	1 x 1GbE LOM and 1 x OCP3 NIC
PCIe slots	Up to 6 x PCIe Gen3 or up to 4 x 16 slots	Up to 8 slots PCIe Gen4 or Gen5 No SNAPI. No CXL.
GPU	Up to 2 x DW GPUs	No GPU support
Integrated Ports	Front: 2 x USB 2.0, 1 x USB micro (iDRAC Direct), primary VGA, status LEDs Rear: 2 x USB 2.0, network, iDRAC9, VGA Optional: Internal USB 3.0	Front: VGA, 1 x USB 2.0, iDRAC Direct micro-USB, ID Button & LED Rear: VGA, 1 x USB 2.0, 1 x USB 3.0, Management RJ-45, 2 x LOM RJ-45, 1 x Serial (optional) Internal: 1 x USB 2.0
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, Fans, PSU, IDSDM and BOSS (2 x internal M.2)	Hot Plug/RAID controlled drives, High Power Air-Cooled Configurations , PSU, BOSS-N1 (2 x M.2 MVMme)
Power Supplies	750W, 1100W, 1600W, 2000W, 2400W	1100W, 1400W , 1800W , 2400W, 2800W
Dimensions	H x W x D: 2U x 434mm x 812mm	H x W x D: 2U x 482mm x 869.06mm
Form Factor	2U Rack Server	2U Rack Server

PowerEdge R960

Extreme Computing Power

- Up to four 4th Generation Intel® Xeon® Scalable processors with up to 60 cores per processor

Support for highest memory speed & capacity

- Up to 64 DDR5 RDIMMs
- Up to 4800 MT/s (1DPC) or 4400 MT/s (2DPC)



Support for up to 36 Drives

- Up to 36 NVMe direct attached drives
- Gen5 NVMe & SAS4 Support
- Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
- Next-gen hardware NVMe RAID

Flexible I/O

- Up to 12 x PCIe Gen 5 Slots
- 1 x OCP 3.0 slot
- Dedicated internal PERC

- Choice of 5 PSU (Gold or Platinum) to achieve sustainable energy goals.
- Optimized for air-cooling in a variety of configurations, optional Dell Direct Liquid Cooling Support
- Support for up to 4 Doublewide GPUs.
- Industry-leading manageability and security.

TARGET WORKLOADS



Large In-Memory Databases

With up to 64 DIMMs to maximize support for in-memory databases



Virtualization/VDI

With 4 CPUs and the greatest capacity for memory, storage, and I/O, this platform is optimal for the densest virtualization stacks



LOB Applications

Flexibility and capacity to support the most demanding Line Of Business applications

MAINSTREAM

Technical Specifications – R940XA, R960

Features	PowerEdge R940XA	PowerEdge R960
CPU	Up to four 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor Support for up to 4 x 205W processors	Up to four 4 th Generation Intel® Xeon® Scalable processors with up to 60 cores per processor. Support for up to 4 x 350W processors
Memory	DDR4: 48x DDR4 RDIMM/LRDIMM Optane Memory (Apache Pass): Yes NVDIMM: Yes	Up to 64 x DDR5 RDIMMs NVDIMM: No DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 32 x 2.5" SAS/SATA HDD/SSDs; or NVMe (Gen3) Internal: IDSDM and BOSS (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS	Up to 32 x 2.5" SAS/SATA HDD/SSDs Up to 24 x 2.5" NVMe SSDs Up to 16 x E3.S NVMe Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot. No IDSM. Bandwidth: Up to 32Gb NVMe/24Gb SAS/6Gb SATA
Storage Controller	HW RAID: PERC 9 / PERC 10; Chipset SATA/SW RAID: Yes	RAID (PERC 11 & 12) SAS / SATA / NVMe / RAID (PERC 11 & 12) SAS3 and SAS4 Chipset SATA/SW RAID: Yes
Network	1 x NDC	1 x 1GbE LOM and 1 x OCP3 NIC
PCIe slots	Up to 12 x PCIe Gen3 or up to 6 x 16 slots	Up to 12 slots PCIe Gen5 No SNAPI. No CXL
GPU	Up to 4 x DW GPUs	Up to 4 DW GPUs (350w each)
Integrated Ports	Front: 2 x USB 2.0, 1 x USB micro (iDRAC Direct), primary VGA, status LEDs Rear: 2 x USB 2.0, network, iDRAC9, VGA Optional: Internal USB 3.0	Front: VGA, 1 x USB 2.0, iDRAC Direct micro-USB, ID Button & LED, QuickSync 2.0 (optional) Rear: VGA, 1 x USB 2.0, 1 x USB 3.0, Management RJ-45, 2 x LOM RJ-45, 1 x Serial (optional) Internal: 1 x USB 2.0
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, Fans, PSU, IDSDM and BOSS (2 x internal M.2)	Hot Plug/RAID controlled drives, High Power Air-Cooled Configurations , PSU, BOSS-N1 (2 x M.2 NVMe)
Power Supplies	1100W, 1600W, 2000W, 2400W	1100W, 1400W , 1800W , 2400W, 2800W
Dimensions	H x W x D: 2U x 434mm x 812mm	H x W x D: 4U x 482mm x 846.87mm
Form Factor	4U Rack Server	4U Rack Server

PowerEdge T560

Exceptional Performance

- Powered by up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor
- Up to 16 x DDR5 RDIMMs (1TB max)
- Up to 4800 MT/s (1DPC) or 4400 MT/s (2DPC)

Designed for high reliability

- Hot-plug BOSS
- Hot-plug HDD/SSD
- Hot-plug redundant power supplies
- PERC 11 & 12, SW and HW RAID, Front, Internal PERC and Add-in Card options

Expandable I/O and Storage

- Faster I/O throughput: PCIe Gen 5
- Increased memory performance with DDR5 4800MT/s
- Increased maximum storage with up to 12 x 3.5" HDD, or 24 x 2.5" SSDs, or 8 x 3.5"/2.5" HDD+ 8 x NVMe SSD

Prepped for data analytics and machine learning

- Up to 2 Double-Wide GPU
- Up to 4 x PCIe Gen 4 slots

Industry-leading manageability and security



TARGET WORKLOADS



Database

Built-in features to enable collaborative applications between groups of people that share information and processes on-site or remotely



Medium Duty Inferencing

Tuned to power medium duty AI or ML tailored inferencing algorithms to drive more timely and accurate business insights.



Virtualization

A perfect choice for medium businesses exploring the advantages of software virtualization.

ROBO / SMB

Technical Specifications – T550, T560

Features	PowerEdge T550	PowerEdge T560
CPU	Up to two 3rd Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Support for up to 2 x 220W processors	Up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor, air-cooled Support for up to 2 x 250W processors
Memory	DDR4: Up to 16 x RDIMM (1TB) DIMM Speed: Up to 3200 MT/s	Up to 16 DDR5 RDIMMs (1TB Max) DIMM Speed: Up to 4800MT/s
Storage (Chassis options)	Up to 8 x 3.5" Hot Plug SATA/SAS HDDs/SSDs Up to 24 x 2.5" Hot Plug SAS/SATA HDDs/SSDs Up to 8 x 3.5" Hot Plug SATA/SASHDDs/SSDs and 8 x NVMe SSDs Optional: TBU in 5.25" bay BOSS-S1 (2 x M.2) for boot Bandwidth: SAS-12Gb, SATA-6Gb	Up to 12 x 3.5" Hot Plug SATA/SAS HDD/SSDs Up to 24 x 2.5" Hot Plug SAS/SATA HDD/SSDs Up to 8 x 3.5" Hot Plug SATA/SAS HDD/SSDs and 8 x NVMe SSDs Optional: TBU in 5.25" bay Internal BOSS-N1 (2 x M.2 NVMe) for boot Bandwidth: SAS-12Gb, SATA-6Gb
Storage Controller	HW RAID: PERC 11 fPERC 10.5/11, SAS3 & SAS4 Chipset SATA/SW RAID	HW RAID: PERC 11 & 12, SAS3 & SAS4 Chipset SATA/SW RAID: Yes
Network	2 x 1GE + 1 x OCP 3.0	2 x 1GE + 1 x OCP 3.0;
PCIe Slots	Up to 5x PCIe Gen 4 slots (all x16) + 1 x PCIe Gen 3 (x8)	3 x16 FH, 1 x8 FH Gen 4 slots and 2 x16 Gen 5 DW slots
GPU	Up to 2 x DW	Up to 2 x DW
Integrated Ports	Front: 2 ports (USB 3.0), 1 iDRAC Direct micro-USB Rear: 1 ports (USB 3.0), 1 ports (USB 2.0), serial (option), network, iDRAC9 GE, secondary VGA, SysID	Front: 2 ports (USB 3.0), 1 iDRAC Direct micro-USB Rear: 1 ports (USB 3.0), 1 ports (USB 2.0), serial (option), network, iDRAC9 GE, secondary VGA, SysID
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (PowerManager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, Fans, PSU	Hot Plug/RAID controlled drives, Fans, PSU
Power Supplies	600W, 800W, -48Vdc-- -60Vdc/1100W, 1400W, 2400W	600W, 700W, 800W, -48Vdc-- -60Vdc/1100W, 1400W, 2400W
Dimension	H x W x D: 459mm x 200mm x 660mm	H x W x D: 459mm x 200mm x 660mm
Form Factor	5U Tower Server	5U Tower Server

Reimagine IT Possibilities...

What's new with our **XS** portfolio?



XS workloads

General purpose workloads

General purpose VDI

Cloud

HPC



R660XS : 1U/2S

Higher density



R760XS: 2U/2S

Flexible storage & acceleration

The best choice for customers seeking the right balance in air-cooled compute for the most popular IT applications.



Thoughtfully crafted

To fit your current infrastructure and deliver the right performance features to support your demanding enterprise applications.



Easily configured

Includes a variety of components that are interchangeable to suit your needs.



A breeze to cool

Equipped with patented Multi-Vector air cooling saving on liquid cooling options.

PowerEdge R760xs

2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores
- Up to 250W

Memory Support

- Up to 16 DDR5 DIMMs (1TB max)
- Up to 4800 MT/s



Flexible storage

- Up to 16 x 2.5" + 8x NVMe or 16 x 2.5" or 12 x 3.5" storage options
- Next Gen HW NVMe RAID (PERC12)
- Hot-plug BOSS-N1 (2 x M.2 NVMe) for boot

Flexible I/O

- Up to 6 x PCIe slots (up to 2 x Gen5)
- 1 x OCP 3.0 slot
- 1 x dedicated internal PERC
- Up to 2 x SW GPU (NVIDIA A2)

- Smart Cooling
- Designed for growing scale-out solutions and air-cooled support
- Industry-leading manageability and security

TARGET WORKLOADS



Virtualization

A perfect choice for medium businesses exploring the advantages of software virtualization.



Medium density VM / VDI

Up to 1TB of memory and plenty of cores, R760xs is perfectly sized for typical virtual machines or VDI instances where minor accelerator support is acceptable.



Software-Defined Storage Node

Up to 24 drives (up to 16x NVME!) for software defined storage deployments.

MAINSTREAM OPTIMIZED

Technical Specifications – R740, R750xs & R760xs

Features	PowerEdge R740	PowerEdge R750xs	PowerEdge R760xs
CPU	Up to two 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor Support for up to 2 x 205W processors	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Support for up to 2 x 220W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor, air-cooled Support for up to 2 x 250W processors
Memory	Up to 24 x DDR4 RDIMMs, LRDIMMs Optane Persistent Memory 100 (Apache Pass): Yes NVDIMM: Yes DIMM Speed: Up to 2933 MT/s	Up to 16 x DDR4 RDIMMs (1TB max) Optane Persistent Memory 200 Series (Barlow Pass): No NVDIMM: No DIMM Speed: Up to 3200 MT/s	Up to 16 x DDR5 RDIMMs (1TB max) NVDIMM: No DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 12 x 3.5" SAS/SATA HDDs Up to 24 x 2.5" SAS/SATA HDD or SSDs Up to 24 x NVMe Internal: iDSDM and BOSS (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS	Up to 12 x 3.5" SAS/SATA HDDs Up to 12 x 3.5" SAS/SATA HDDs + 2 x 2.5" Rear Up to 16 x 2.5" SAS/SATA HDDs or SSDs Up to 16 x SAS/SATA HDDs or SSDs + 8 x NVMe HW NVMe RAID (8 x 2.5" with PERC H755N) Rear BOSS-S2 (2 x M.2) for boot Internal: iDSDM or USB Bandwidth: 12Gb/6Gb SAS, SATA 6Gb	Up to 8 x 3.5" SAS/SATA / ChipSATA Up to 12 x 3.5" SAS/SATA HDDs Up to 8 x 2.5" SAS/SATA HDD/SSDs Up to 16 x 2.5" SAS/SATA HDD/SSDs or NVMe SSDs Up to 16 x 2.5" SAS/SATA HDD/SSDs + 8x2.5" NVMe SSDs Rear: 2 x 2.5" (limited configs) SAS / SATA / NVMe (PERC 11 & 12) Rear Hot-plug BOSS-N1 (2 x M.2 NVMe) for boot Internal: USB. No iDSDM
Storage Controller	HW RAID: PERC 9/PERC 10; Dual PERC option Chipset SATA/SW RAID: Yes	HW RAID: PERC 10.5 & 11 (no dual PERC option) HW NVMe RAID Chipset SATA/SW RAID: Yes	SATA / SAS / NVMe / RAID (PERC 11 & 12) SAS3 & SAS4 Chipset SATA/SW RAID: Yes
Network	1 NDC	2 x 1GbE LOM + 1 x OCP 3.0	2 x 1GbE LOM + 1 x OCP 3.0
PCIe Slots	Up to 8 x PCIe Slots Gen3 (4 x 16)	Up to 5 x PCIe Gen4 (5 x16), 1 x PCIe Gen3 (1:x8) with SNAP I/O option	Up to 6 x PCIe Slots: (up to 3 x16LP Gen4 + 1 x 8LP Gen4 + 2 x16 Gen5 LP) No SNAP I
GPU	3 x 300 (DW) or 6 x 75W (SW)	None	Up to 2 x 75W (SW) HL/HH GPU (A2 NVIDIA cards)
Integrated Ports	Front: 2 x USB 2.0, 1 managed (micro-USB) +1 x USB 3.0 (optional) +1 x VGA Rear: 1 x Dedicated iDRAC network port, 1 x Serial, 2 x USB3.0, 1 x VGA	Front: 2 x USB 2.0, 1 managed (micro-usb), primary VGA Rear: 1 ports (USB 3.0), 1 ports (USB 2.0), serial (option), network, iDRAC9, secondary VGA, SysID	Front: VGA, 1 x USB 2.0, iDRAC Direct micro-USB, ID Button & LED; QuickSync 2 (optional) Rear: VGA, 1 x USB 2.0, 1 xUSB 3.0, Management RJ-45, 2 xLOM RJ-45, 1 x Serial (optional) Internal: 1 x USB 2.0
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (PowerManager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (PowerManager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, PSU, fans, iDSDM, BOSS (2 x Internal M.2)	Hot Plug/RAID controlled drives, PSU, fans, iDSDM and BOSS-S2 (2 x M.2) for boot	Hot Plug/RAID controlled drives, PSU, fans and BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	495W, 750W, 1100W, 1600W, 2000W, 2400W	600W, 800W, 1100W, -48Vdc/1100W, 1400W	600W, 700W, 800W, 1100W, -48Vdc/ 1100W, 1400W, 1800W
Dimension	H x W x D: 2U x 434mm x 716mm	H x W x D: 2U x 434mm x 721mm	H x W x D: 2U x 434mm x 721mm
Form Factor	2U Rack server	2U Rack Server	2U Rack Server

PowerEdge R660xs

2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor
- Up to 250W

Memory Support

- Up to 16 DDR5 DIMMs (1TB max)
- Up to 4800 MT/s



Flexible storage

- Up to 10 x SAS/SATA/NVMe drives or up to 4 x 3.5" high-capacity SATA HDDs
- Next Gen HW NVMe RAID (PERC12)
- USB and Internal BOSS-N1 (2 x M.2 NVMe) for boot

Flexible I/O

- Up to 3 x PCIe slots
- 1 x OCP 3.0 slot
- 1 x dedicated internal PERC

- Smart Cooling
- Designed for growing scale-out solutions and air-cooled support
- Industry-leading manageability and security

TARGET WORKLOADS



Virtualization / Cloud

Medium density virtualization and Cloud-Native requiring low-medium local storage.



Scale-Out Database

Medium Duty traditional database & scale out database with low-medium local storage



High Performance Compute

HPC requiring 1DPC design for highest memory performance & scale out clusters.

MAINSTREAM OPTIMIZED

Technical Specifications – R640, R650xs & R660xs

Features	PowerEdge R640	PowerEdge R650xs	PowerEdge R660xs
CPU	Up to two 2 nd Generation Intel Xeon Scalable processors with up to 28 cores per processor, air-cooled Support for up to 2 x 205W processors	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 32 cores per processor, air-cooled Support for up to 2 x 220W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor, air-cooled Support for up to 2 x 250W processors
Memory	Up to 24 x DDR4 RDIMM, LRDIMM Optane Persistent Memory 100 (Apache Pass): Yes NVDIMM: Yes DIMM Speed: Up to 2933 MT/s	Up to 16 x DDR4 RDIMMs (1TB max) Optane Persistent Memory 200 Series (Barlow Pass): No NVDIMM: No DIMM Speed: Up to 3200 MT/s	Up to 16 x DDR5 RDIMMs (1TB max) NVDIMM: No DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 4 x 3.5" SAS/SATA HDDs Up to 10 x 2.5" SAS/SATA HDDs or SSDs, or NVMe Up to 2 x 2.5" (rear) SAS/SATA HDDs or SSDs, or NVMe Internal iDSDM and BOSS (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS	Up to 4 x 3.5" SAS/SATA HDDs Up to 10 x 2.5" SAS/SATA HDDs or SSDs, or NVMe Up to 2 x 2.5" (rear) SAS/SATA HDDs or SSDs, or NVMe Up to 8 x 2.5" NVMe RAID HW NVMe RAID (8 x 2.5" with PERC H755N) Internal: iDSDM, USB and BOSS-S1 (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS, SATA 6Gb	Up to 4 x 3.5" SAS/SATA / ChipSATA Up to 8 x 2.5" SAS/SATA HDD/SSDs Up to 10 x 2.5" SAS/SATA HDD/SSDs or NVMe SSDs Rear: 2 x 2.5" SAS / SATA / NVMe w/ NVMe RAID (PERC 11 & 12) Internal: USB and Internal BOSS-N1 (2 x M.2 NVMe) for boot. No iDSDM
Storage Controller	HW RAID: PERC 9 / PERC 10; Dual PERC option Chipset SATA/SW RAID: Yes	HW RAID: PERC 10.5 & 11 (no Dual PERC option) HW NVMe RAID Chipset SATA/SW RAID: Yes	SATA / SAS / NVMe / RAID (PERC 11 & 12) SAS3 and SAS4 Chipset SATA/SW RAID: Yes
Network	1 NDC	2 x 1GbE LOM + 1 x OCP 3.0	2 x 1GbE LOM + 1 x OCP 3.0
PCIe Slots	Up to 3 x PCIe Gen3 (x16/x16/x16) or 2 x PCIe FH slots (Gen3)	Up to 3 x PCIe Gen4 (x16/x8/x8) with SNAP1 I/O option	Up to 3 x PCIe Gen4 (x16/x8/x8) or up to 2 x PCIe Gen5 (x16/x8) No SNAP1
GPU	Up to 3 SW GPUs	None	None
Integrated Ports	Front: 1 x USB 2.0, 1 managed (micro-USB) + front VGA Rear: 1 x Dedicated iDRAC network port, 1 x Serial, 2 x USB 3.0, 1 x VGA Optional Internal USB	Front: 2 x USB 2.0, 1 managed (micro-usb) + front VGA Rear: 1 x USB 3.0, 1 ports (USB 2.0) serial (option), network, iDRAC9, secondary VGA, SysID	Front: VGA, 1 x USB 2.0, iDRAC Direct micro-USB, ID Button & LED; QuickSync 2.0 (optional) Rear: VGA, 1 x USB 2.0, 1 x USB 3.0, Management RJ-45, 2 x LOM RJ-45, 1 x Serial (optional) Internal: 1 x USB 2.0
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (PowerManager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (PowerManager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, 2 Tiered Fans, PSU, iDSDM, BOSS (2 x Internal M.2)	Hot Plug/RAID controlled drives, Cold plug fans, PSU, iDSDM and (non-hot-plug) BOSS-S1 (2 x M.2) for boot	Hot Plug/RAID controlled drives, PSU. Hot-plug fans, Internal (non-hot-plug) BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	495W, 750W, 1100W, 1600W	600W, 800W, 1100W, -48Vdc/ 1100W, 1400W	600W, 700W, 800W, 1100W, -48Vdc/ 1100W, 1400W, 1800W
Dimension	H x W x D: 1U x 434mm x 773mm	H x W x D: 1U x 434mm x 698mm (2.5" drives) or 749mm (3.5" drives)	H x W x D: 1U x 434mm x 698mm (2.5" drives) or 749mm (3.5" drives)
Form Factor	1U Rack Server	1U Rack Server	1U Rack Server

Reimagine IT Possibilities...

What's new with our **AMD 1 socket** portfolio?



Workloads

Data analytics

Software defined storage

Dense Virtualization



R6615 : 1U/1S

Most dense 1S offer



R7615: 2U/1S

Maximized PCIe & Storage

Greater memory footprint with flexible storage and outstanding performance per dollar invested.



Wise Investment

With one AMD EPYC™ 4th gen enables DDR5 memory, PCIe Gen 5 all in an air-cooled and smaller footprint.



More virtual machine density

Packed with 50% more CPU cores and supports up to 6 GPUs for VDI consolidation.



Increased scalability

Store more data per server with 33% more E3.S drives and save precious data center floor space.

PowerEdge R7615

The only socket you need

- Powered by one 4th Generation AMD EPYC™ processor with up to 96 cores per processor
- Up to 12 x DDR5 RDIMMs (3TB max)

I/O and connectivity

- Up to 8 x PCIe slots (up to 4 x Gen5)
- OCP 3.0 for network cards



Flexible storage

- Up to 12 x 3.5" – 12Gb SAS, 6Gb SATA
- Up to 24 x 2.5" – 12Gb SAS, 6Gb SATA, NVMe
- Up to 32 x E3.S – NVMe
- Rear: Up to 4 x 2.5" Hot Plug SAS/SATA or NVMe HDDs, Up to 4 x E3.S NVMe
- Internal BOSS-N1 (2 x M.2 NVMe) for boot

- Smart Cooling
- Direct Liquid Cooling (DLC) Support
- Industry-leading manageability and security

TARGET WORKLOADS



SDS

Direct connect SAS/SATA/NVMe



Virtualization

High core count performance for highest VM density in 1S



Data Analytics

Multi-die architecture offers low latency and floating point capacity for Big Data and Containers

MAINSTREAM OPTIMIZED

Technical Specifications – R7515, R7615

Features	PowerEdge R7515	PowerEdge 7615
CPU	One 2 nd or 3 rd Generation AMD EPYC™ processor with up to 64 cores per processor Up to one 280W (cTDP)	One 4 th Generation AMD EPYC™ processor with up to 96 cores per processor Target up to 400W (cTDP)
Memory	DDR4: Up to 16 x DDR4 RDIMM, LRDIMM (2TB) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 12 x DDR5 RDIMM (3TB) DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 8 x 3.5" Hot Plug SATA/SAS HDDs Up to 12 x 3.5" Hot Plug SAS/SATA HDDs Up to 24 x 2.5" Hot Plug SATA/SAS/NVMe Rear: Up to 2 x 3.5" Hot Plug SAS/SATA HDDs Internal: 2 x M.2 (BOSS)	Up to 24 x 2.5" SAS/SATA HDD or SSD, or NVMe Up to 12 x 3.5" SAS/SATA HDD or SSD Up to 32 E3.S NVMe Rear: Up to 4 x 2.5" Hot Plug SAS/SATA or NVMe HDDs, Up to 4 x E3.S NVMe Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot Bandwidth: 12Gb/6Gb SAS
PCIe Storage	Up to 24 NVMe (Up to 12 NVMe Direct)	Up to 32 E3.S NVMe Direct
Storage Controller	HW RAID: PERC 9/10 - HBA330, H330, H730P, H740P, H840, 12G SAS HBA Chipset SATA/SW RAID(S150): Yes	HW RAID: PERC11, PERC12 HW NVMe RAID: PERC11, PERC12 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE; 2 x 10GbE BT; 2 x 10GbE SFP+; 2 x 25GbE SFP28	LOM Riser + 1 x OCP 3.0
PCIe slots	Up to 4 PCIe: 2 PCIe Gen3; 2 PCIe Gen4	Up to 8 x PCIe x16 slots, 4 x PCIe Gen5, 4 x PCIe Gen4
GPU	Up to 4 Single-Wide GPU(T4); Up to 1 Full-Height FPGA	Up to 3 500W DWFL (Target 700W) or up to 6 150W SWFL
Integrated Ports	Front: 2 ports (USB 2.0), 1 (micro-USB, iDRAC Direct) Rear: 2 ports (USB 3.0) Internal: 1 port (USB 3.0)	Front: 1 port (USB 2.0), 1 (iDRAC Direct micro-USB) Rear: 1 port (USB 3.0) + 1 port (USB 2.0)
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	16G iDRAC Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug Hard drives, PSUs, iSDSM, Boot Optimized Storage Subsystem (BOSS)	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	495W, 750W, 1100W, 1600W	700W, 800W -48Vdc, 1100W, 1100W -48Vdc 1400W 1800W, 2400W
Dimensions	H x W x D: 2U x 434mm (17.08 in) x 681.75 mm (26.84 in)	H x W x D: 2U x 434mm (17.08 in) x 736.29 mm (28.98 in)
Form Factor	2U Rack Server	2U Rack Server

Reimagine IT Possibilities...

What's new with our R660/R760 portfolio?



Workloads

Data center standardization

High density virtualization

Online transaction processing

Database analytics

Virtual desktop infrastructure

In-memory database



R660 : 1U/2S

Denser 2 socket



R760: 2U/2S

Maximum configuration flexibility

Provides performance and versatility as needed to address your most demanding applications



Max Performance

Extract value faster from collected data with high-performance processors, GPUs, next-generation storage for demanding workloads like AI/ML



Air cooled at peak performance

Take advantage of configurations with high performance CPUs in an air-cooled chassis



Gain agility

Can be deployed for maximum scalability in vSAN (HCI) environments or for maximum application performance in bare metal environments with the new PERC12

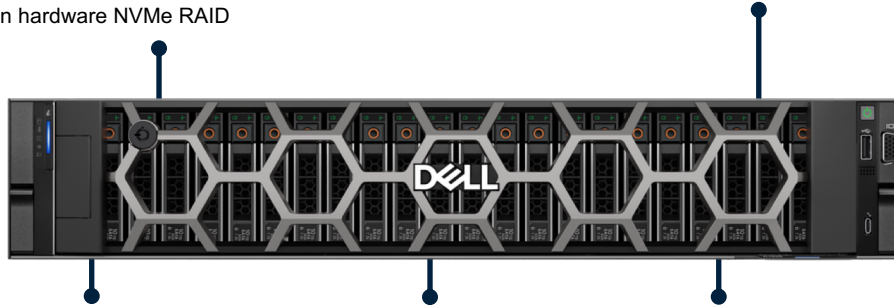
PowerEdge R760

Support for up to 28 Drives

- 24 NVMe direct-attached drives
- Gen5 NVMe* & SAS4 support
- Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
- Next-gen hardware NVMe RAID

Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- Up to 4800 MT/s (1DPC) or 4400 MT/s (2DPC)



2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor
- High-bandwidth memory CPUs

Support for GPU

- 2 x 300W (DW) or 6 x 75W (SW)

Flexible I/O

- Up to 8 x PCIe Slots
- Optional 2 x 1GbE LOM + 1 x OCP 3.0 slot

- Smart Cooling
- Direct Liquid Cooling
- Designed for growing scale-out solutions and air-cooled support
- Industry-leading manageability and security

TARGET WORKLOADS



High Performance Scale-Out Databases

Architect for growth and scalability using high core count CPUs with the latest DDR5 memory technology, high-bandwidth networking and Gen5 based NVMe storage.



Next Level of Virtualization

8TB of memory combined with 112 cores of the latest generation Intel CPU enables high-density virtualization in a 2S server..



Accelerated AI Training

With the latest Gen5 PCIe enabled NVIDIA GPUs and NVMe drives designed to offer the highest throughput on the largest datasets, customers benefit from reduced training cycles and faster AI deployments.

MAINSTREAM

Technical Specifications – R740/XD, R750 & R760

Features	PowerEdge R740/XD	PowerEdge R750	PowerEdge R760
CPU	Up to two 2 nd Generation Intel® Xeon® Scalable processors with up to 28 cores per processor Support for up to 2 x 205W proc	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 40 cores per processor Support for up to 2 x 270W processors Direct Liquid Cooling support	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors Direct Liquid Cooling support
Memory	Up to 24 x DDR4 RDIMM, LRDIMM, Optane Persistent Memory 100 (Apache Pass): Yes NVDIMM: Yes DIMM Speed: Up to 2933 MT/s	Up to 32 x DDR4 RDIMMs/LRDIMMs (8TB + Optane Persistent Memory 200 Series) Optane Persistent Memory 200 Series (Barlow Pass): Yes DIMM Speed: Up to 3200 MT/s corrected	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 12 x 3.5" SAS/SATA HDDs Up to 24 x 2.5" SAS/SATA HDD/SSDs Up to 24 x NVMe SSDs Internal: iDSDM and BOSS (2 x M.2) for boot Bandwidth: 12Gb/6Gb SAS, SATA 6Gb	Up to 12 x 3.5" SAS/SATA HDDs Up to 24 x 2.5" SAS/SATA HDD/SSDs or NVMe SSDs with universal slots Up to 16 x 2.5" SAS/SATA HDD/SSDs + 8 x 2.5" NVMe SSDs Up to 4 x rear 2.5" SAS/SATA HDD/SSDs or NVMe SSDs Rear BOSS-S2 (2 x M.2 SATA) for boot Internal: iDSDM or USB Bandwidth: 12Gb/6Gb SAS, SATA 6Gb	Up to 12 x 3.5" SAS/SATA HDDs Up to 24 x 2.5" SAS/SATA HDD/SSDs Up to 16 x 2.5" SAS/SATA HDD/SSDs + 8 x 2.5" NVMe SSDs Up to 4 x rear 2.5" SAS/SATA HDD/SSDs or NVMe SSDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot Internal: iDSDM or USB Bandwidth: Up to 32Gb NVMe/24Gb SAS/6Gb SATA
Storage Controller	HW RAID: PERC 9 & PERC 10 (dual PERC option) Chipset SATA/SW RAID: Yes	HW RAID: PERC 10.5 & 11 (dual PERC option) HW NVMe RAID Chipset SATA/SW RAID: Yes	HW RAID: PERC 11 & 12 (dual PERC option) HW SAS4/SATA/NVMe RAID SW RAID: Yes
Network	1 NDC 4 x 1GbE, 4 x 10GbE, 2 x 10GbE + 2 x 1GbE, or 2 x 25GbE	2 x 1GbE LOM + 1 x OCP 3.0	Optional 2 x 1GbE LOM, 1 x OCP 3.0
PCIe Slots	Up to 8 x PCIe Slots Gen3 (4 x 16)	Up to 8 x PCIe Slots Gen4 (up to 6 x 16), SNAP I/O option	Up to 8 x PCIe Slots (Gen4 / Gen5), SNAP I/O option
GPU	3 x DW or 6 x SW	2 x DW or 6 x SW	2 x DW or 6 x SW
Integrated Ports	Front: 2 x USB 2.0, 1 x iDRAC Direct micro-USB port, 1 x USB 3.0 (optional), 1 x VGA Rear: 1 x Dedicated iDRAC Ethernet port, 1 x Serial, 2 x USB 3.0, 1 x VGA Internal USB	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB port, 1 x USB 3.0 (optional), 1 x VGA Rear: 1 x Dedicated iDRAC Ethernet port, 1 x Serial (optional), 1 x USB 3.0, 1 x USB 2.0, 1 x VGA (optional for Liquid Cooling configurations) Internal USB	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB port, 1 x USB 3.0 (optional), 1 x VGA Rear: 1 x Dedicated iDRAC Ethernet port, 1 x Serial (optional), 1 x USB 2.0, 1 x USB 3.0, 1 x VGA (optional for Liquid Cooling configurations) Internal: USB (optional)
System Management	iDRAC9, iDRAC Direct, iDRAC RESTful with Redfish, Quick Sync 2 wireless module (optional), OpenManage Enterprise and Power Manager, OpenManage Mobile	iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, Quick Sync 2 wireless module, OpenManage Enterprise and Power Manager, OpenManage Mobile	iDRAC9, iDRAC Direct, iDRAC RESTful API with Redfish, iDRAC Service Module, Quick Sync 2 wireless module, OpenManage Enterprise and Plugins (Power Manager, SupportAssist, Update Manager), OpenManage Mobile
High Availability	Hot Plug/RAID controlled drives, PSU, Hot-plug fans	Hot Plug/RAID controlled drives, PSU, Hot-plug fans. Hot-plug BOSS	Hot Plug/RAID controlled drives, PSU, Hot-plug fans. Hot-plug BOSS
Power Supplies	AC (Platinum): 495W, 750W, 1100W, 1600W, 200W, 2400W, AC (Titanium): 750W LVDC @-48VDC Input: 1100W	AC (Platinum): 800W, 1400W, 2400W AC (Titanium): 1100W LVDC @-48VDC Input: 1100W	AC (Platinum): 800W, 1400W, 2400W AC (Titanium): 700W, 1100W, 1800W, 2800W LVDC @-48VDC Input: 1100W
Dimension	H x W x D: 86.8mm x 482mm x 737.5mm	H x W x D: 86.8mm x 482mm x 758mm	H x W x D: 86.8mm x 482mm x 758mm
Form Factor	2U Rack Server	2U Rack Server	2U Rack Server

Reimagine IT Possibilities...

What's new with our **AMD 1 socket** portfolio?



Workloads

Data analytics

Software defined storage

Dense Virtualization



R6615 : 1U/1S

Most dense 1S offer



R7615: 2U/1S

Maximized PCIe & Storage

Greater memory footprint with outstanding performance per dollar invested.



Wise Investment

With one AMD EPYC™ 4th gen enables DDR5 memory, PCIe Gen 5 all in an air-cooled and smaller footprint.



More virtual machine density

Packed with 50% more CPU cores and supports up to 6 GPUs for VDI consolidation.



Increased scalability

Store more data per server with 33% more E3.S drives and save precious data center floor space.

PowerEdge R6615

The only socket you need

- Powered by one 4th Generation AMD EPYC™ processor with up to 96 cores per processor
- Up to 12 x DDR5 RDIMMs (3TB max)

I/O and connectivity

- Up to 3 x PCIe slots (up to 2 x Gen5)
- OCP 3.0 for network cards



Flexible storage

- Up to 4 x 3.5" SAS/SATA or SSD
- Up to 10 x 2.5" SAS/SATA, SSD; or NVMe
- Up to 14 x E3.S Hot Plug NVMe
- HW NVMe RAID
- Internal BOSS-N1 (2 x M.2 NVMe) for boot

- Smart Cooling
- Direct Liquid Cooling (DLC) Support
- Industry-leading manageability and security

TARGET WORKLOADS



Virtualization

Improved TCO with VM density and SQL performance improvements



HCI

High parallelism for low latency on ROBO VxRail and Dense Azure Stack HCI



NFV

OpenStack Ready Architecture applicable for Telco

MAINSTREAM OPTIMIZED

Technical Specifications – R6515, R6615

Features	PowerEdge R6515	PowerEdge R6615
CPU	One 2 nd or 3 rd Generation AMD EPYC™ processor with up to 64 cores per processor Up to one 280W (cTDP)	One 4 th Generation AMD EPYC™ processor with up to 96 cores per processor Target up to 400W (cTDP)
Memory	DDR4: Up to 16 x DDR4 RDIMM, LRDIMM (2TB) DIMM Speed: Up to 3200 MT/s	DDR5: Up to 12 x DDR5 RDIMM (3TB) DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 4 x 3.5" Hot Plug SAS/SATA HDDs Up to 10 x 2.5" Hot Plug SAS/SATA/NVMe Up to 8 x 2.5" Hot Plug SAS/SATA SSD's Internal: Option 2 x M.2 (BOSS)	Up to 4 x 3.5" Hot Plug SAS/SATA HDDs Up to 12 x 2.5" (10 Front + 2 Rear) Hot Plug SAS/SATA HDD/SSD's or NVMe Up to 14 x E3.S Hot Plug NVMe CPU Direct or 16 x E3.S Hot Plug NVMe with Dual Controllers Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot Bandwidth: 12Gb/6Gb SAS
PCIe Storage	Up to 10 NVMe Direct	Up to 14 E3.S NVMe Direct or 16 x E3.S Hot Plug NVMe with Dual Controllers
Storage Controller	HW RAID: PERC 9/10 - HBA330, H330, H730P, H740P, H840, 12G SAS HBA Chipset SATA/SW RAID (S150): Yes	HW RAID: PERC11 , PERC12 HW NVMe RAID: PERC11 , PERC12 Chipset SATA/SW RAID: Yes
Network	2 x 1GbE LOM + 1 x OCP 3.0; 2 x 10GbE BT; 2 x 10GbE SFP+; 2 x 25GbE SFP28	LOM Riser + 1 x OCP 3.0
PCIe slots	Up to 2 PCIe: 1 PCIe Gen3; 1 PCIe Gen4	Up to 3 x PCIe x16 slots, 2 x PCIe Gen5, 1 x PCIe Gen4
GPU	Up 2 Single-Wide GPU (T4)	Up to 3 75W LP or 2 150W FH/HL
Integrated Ports	Front: 1 ports (USB 2.0), 1 (micro-USB, iDRAC Direct) Rear: 2 ports (USB 3.0) Internal: 1 port (USB 3.0)	Front: 1 port (USB 2.0), 1 (iDRAC Direct micro-USB) Rear: 1 port (USB 3.0) + 1 port (USB 2.0)
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	16G iDRAC Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug Hard drives, PSUs, iDSMD, Boot Optimized Storage Subsystem (BOSS)	Hot Plug/RAID controlled drives, Fans, PSUs, BOSS-N1 (2 x M.2 NVMe) for boot
Power Supplies	550W, 700W	700W , 800W , 1100W , 1100W -48Vdc , 1400W , 1800W
Dimensions	H x W x D: 1U x 606.5mm (23.9") or 657.3mm (25.9")	H x W x D: 1U x 434mm (17.08 in) x 736.29 mm (28.98 in)
Form Factor	1U Rack Server	1URack Server

Accelerate anywhere

- Dell's 'built-for-the-edge' server portfolio
- Short-depth to fit in field cabinets & racks (<19")
- Front-facing I/O to make servicing in tight spaces easier for field engineers
- Shock, vibration, dust, and thermally rated for harsh and unpredictable edge environments (MIL/NEBS)
- Dell ecosystem-enabled with iDRAC

Monolithic

XR7620

- 450mm 2U, 2S Intel® Xeon® Scalable Processors
- Supports 2 x 300W GPUs for AI at Edge
- GPU and CPU-optimized configurations to handle multitude of edge-use cases
- -5C to 55C operating temperature



XR5610

- 400mm class 1U, 1S Intel® Xeon® Scalable Processor
- Right-sized for on-site dedicated workloads
- Telco-optimized configuration with time & sync card available
- -5C to 55C operating temperature



Multi-node

XR4000

- 2U multi-node with Intel® Xeon® D (Dell 1st)
- Dell shortest-depth server at 350mm
- Nano witness-node allows for VM-cluster in single box
- Rackable, stackable, and wall-mountable for ultimate deployment flexibility
- -5C to 55C operating temperature



XR8000

- 430mm 2U multi-node with 1S Intel® Xeon® Scalable and Xeon Edge Enhanced processor options
- Telco-optimized for DU and CU RAN deployments
- Extensible to multitude of enterprise edge use cases
- -5C to 55C operating temperature



Enterprise Edge Server Ecosystem (16G)

Heavy Compute/Storage

Latency Reduction

Workload Consolidation

Dedicated Workloads

Translation

Data Creation

RACK SERVERS

Traditional

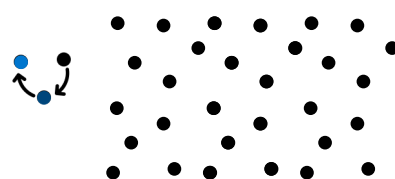
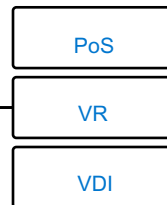
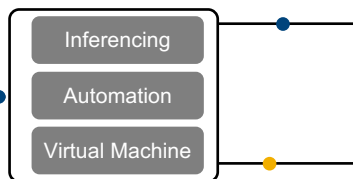
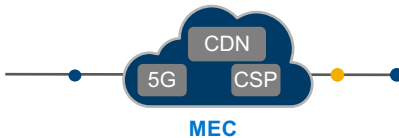
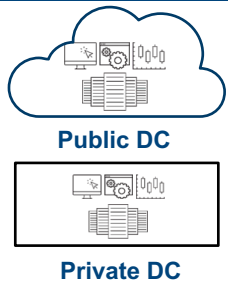


EDGE SERVERS

Hardened



IoT/ Devices



Core

Near Edge

Edge

Far Edge

iDrac/OpenManage

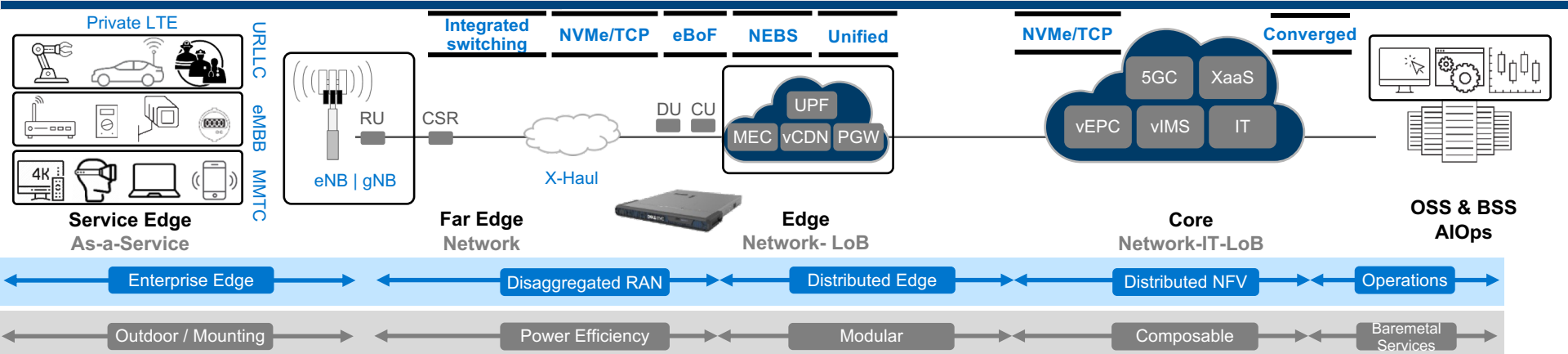
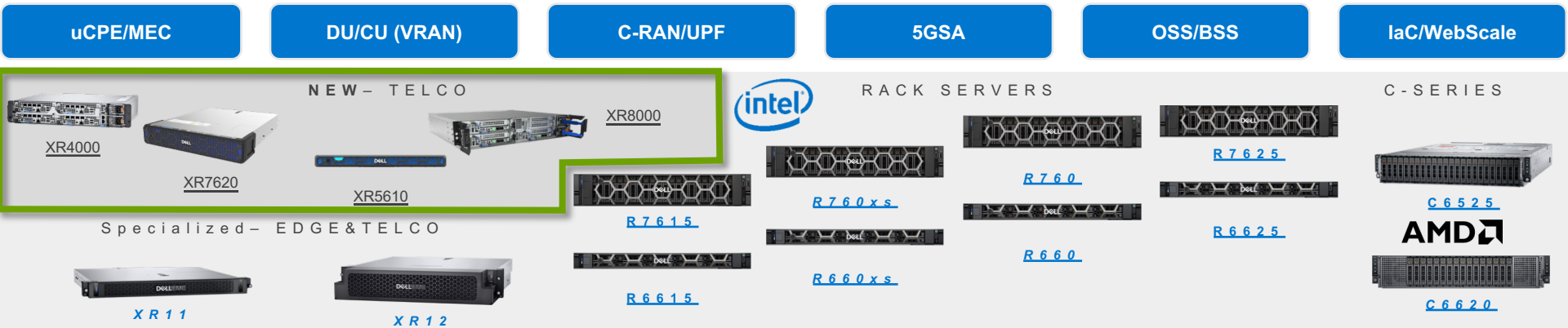
Dell APEX

Dell Edge Solutions

Dell Frontier

DELL Technologies

Telecom Server Ecosystem



Reimagine IT Possibilities...

Dell Technologies' most versatile edge server



Workloads

VDI

Machine vision

Video surveillance

vSAN / VM

Point-of-sale

Data compression

XR4000: 2U 4-Node Edge Server



Rackable chassis for rack-mounted deployments



Stackable flex mount chassis for everywhere else

Experience ultimate flexibility for your edge deployments with Dell's shortest-depth server



New Nano Server

Create a self-contained 2-node vSAN cluster in a footprint not much larger than a shoebox with dell Nano Witness Server included in-chassis



Multi-node design

XR4000 utilizes a unique sled design, offering up to 4 totally independent server nodes in a single 2U chassis



Purpose built for the edge

Small but mighty this server can handle temp ranges from -5C to 55C and is rated to MIL 810H and NEBS Level 3

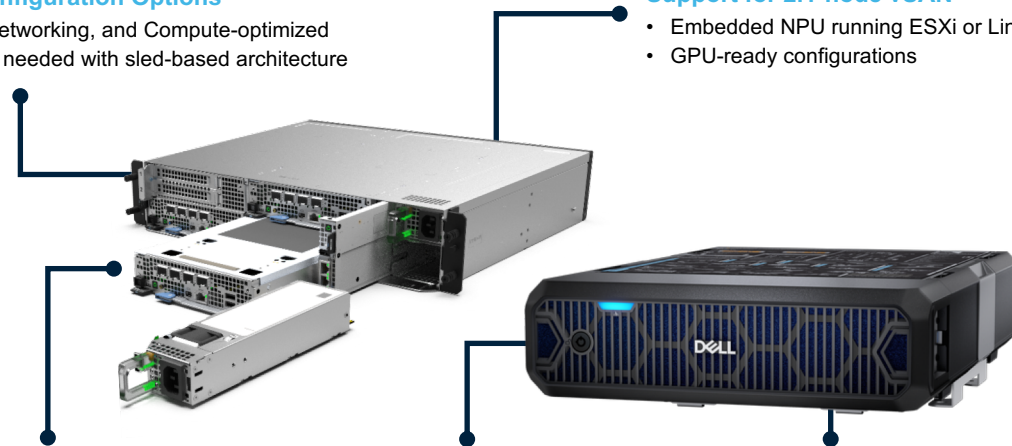
PowerEdge XR4000

Flexible Configuration Options

- Storage, Networking, and Compute-optimized
- Expand as needed with sled-based architecture

Support for 2.1-node vSAN

- Embedded NPU running ESXi or Linux
- GPU-ready configurations



Single Socket 3rd Generation Intel® Xeon® D

Intel® Xeon® D processor, up to 20C per node

Intelligent Filtered Bezel

- Secure Locking Bezel
- Filter monitored by iDRAC

Flexible Mounting Options

- Multiple systems securely stack
- VESA bracket compatible
- DIN Rail adapter option

- Up to 4 discrete servers in a single 2U chassis
- -5C to 55C operating temperature
- Short-depth 350mm from ear-to-rack
- Front and Rear I/O options

TARGET WORKLOADS



Retail

Perfect for POS, Store of the Future, IoT, AI Inferencing, and many others



Military

Highly portable and light enough for single-person carry. Hardened for dusty, hot/cold operations

MIL 810H, 461G, 901E, 1474E rated (limited configurations)



Manufacturing

Ideal for machine aggregation, VDI, AI inferencing, OT/IT translation, industrial automation, ROBO, and more

EDGE / TELCO

Technical Specifications – XR4000

Features

PowerEdge XR4000

CPU	3 rd Generation Intel® Xeon® D processors Up to 20 cores at 120W
Memory	Up to 4 x DDR4 RDIMMs/LRDIMMs DIMM Speed: Up to 3200 MT/s Minimum 1DPC per channel
Storage (Chassis options)	4 x M.2 NVMe (1U) 12 x M.2 NVMe (2U) Up to 3.84TB capacity Read Intensive SSD drives (for general storage use) 800GB capacity Mixed Use SSD drives (for vSAN cache)
Storage Controller	BOSS-N-1 (2 x M.2 NVMe)
Network	4 x 10GbE or 4 x 25 GbE LOM
PCIe slots	2 slots x16 PCIe Gen 4; up to 240W
GPU	2 x 300W (DW) or 4 x 150W (SW)
Integrated Ports	iDRAC rj45 & Micro USB 2 x USB Mini DP
System Management	iDRAC Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager); iDRAC Direct
High Availability	Hot plug redundant PSUs
Power Supplies	2 x 60mm – 1400W MM AC (110v & 220v) or 1100W -48vDC
Dimensions	H x W x D: 2U x 434mm x 355mm (2U x 267mm x 355mm)
Form Factor	2U Rack Server
Operating Environments	-5C to 55C (restricted configs)
Certs and Tests	MIL-STD (810H, 461G, 901E, 1474E) and NEBS 3 (GR3108 Class 1, GR-1089, GR-63)

Dell Edge Gateway 5200

Rich Storage

- 2 x 2.5" SATA

Intel 9th Gen – Quad Core

- Intel Core-i (i3, i5 and i7)
- Up to 64GB DDR4 memory

Expansion

- CANbus
- 2 x GbE PoE out
- 2 x Isolated Serial COM
- 2 x Isolated GbE
- DIO

Security

- TPM 2.0
- Intel AMT

Front accessible I/O and Adaptive uFM module

- RS-232/422/485
- 3 x GbE
- 3 x USB 3 and 3 x USB 2
- 2 x DP++/DVI/VGA
- 4 x Serial COM
- 8-ch DI
- 8-ch DO

- 0°C to 60°C operating temperature
- Compact, Fan-less and Rugged Design
- WiFi-6E, Bluetooth 5.2 and **Certified** Dual Nano SIM **4G & 5G** options
- OEM ready options

TARGET WORKLOADS



Manufacturing

Simplify and automate data collection at every stage of the production cycle



Telecom

Accelerate innovation and revenue growth with new services



Retail

Personalize customer experience with data insights



Smart Cities

Improve quality of life by increasing the city's efficiency

EDGE/TELCO

Technical Specifications – PC 5000, EGW5200

Features	Embedded PC 5000	Edge Gateway 5200
CPU	Core i3, Core i5, and Core i7-6820EQ or Celeron	Core i3-9100TE, Core i5-9500TE, and Core i7-9700TE
Memory	4GB, 8GB, 16GB to 32GB DDR4	2 x DDR4 SO-DIMM socket, supporting up to 32GB DDR4 per socket, for a total of 64GB
Storage (Chassis options)	500GB & 1TB HDD 32GB, 64GB & 128GB SSD	64GB, 128GB, 256GB, 512GB, 1TB, 2TB 2.5" SSD (Max: 4TB, 2+2)
Display	1 x HDMI 1 x VGA 2 x DP	2 x DP++ 1 x DVI-D 1 x VGA
Ethernet	2 x Gigabit Ethernet: 2 x RJ-45	3 x Intel GbE (2 x i225 + i219LM PHY, iAMT supported on i5 and i7 CPUs)
Serial Ports	3 x COM Ports	2 x COM Ports (RS-232/422/485) 2 x COM Ports (RS-232)
DI/O	N/A	8-ch DI and 8-ch DO
USB	4 x USB 3.0 4 x USB 2.0	6x external USB ports (2 x USB 3.1 Gen 2, 1 x USB 3.1 Gen 1, 3 x USB 2.0), one internal USB 2.0 port
Audio	Mic-in, Line-in, Line-out	Line-out, mic-in
Mini PCIe		1 x full size (USB 2.0 + PCIe), used for WiFi by default
M.2	2 PCI/PCIe slots: riser card options: 2 x PCI, 1 x PCI + 1 x PCIe x 16 or 2 PCIe x8	1 x socket 2, key B+M or B, 1 x 2280/3042 (USB 3.1 + SATA 6 Gb/s + 2 x PCIe)
Power Supply	Nominal input 24V DC (12-26V). Also accepts Dell AC adapter, 180W with locking plug	DC Input 12–24 VDC (±10% tolerance) - Standard AC Input Optional: 180 W, 60 W (for PoE) external AC/DC adapter
Wireless	Wi-Fi IEEE 802.11n Bluetooth LE	WiFi-6E Bluetooth 5.2
WWAN	3G or LTE	Dual NanoSIM (exterior): 4G & 5G certified GNSS (GPS)
Operating Environment	0°C to 60°C, with airflow 0.7 m/s	0°C to 60°C, with airflow 0.6 m/s
Environmental Certs and Tests	ASTM-D4169-04, Random Operational Vibration, 0.52grms MIL-STD-810G, Method 514.6, Procedure 1, Cat 4 40G, MIL-STD-810G, Method 514.7, Procedure 1 (Shock)	MIL-STD-810G METHOD 514.6 category 4 - common carrier (US highway truck vibration exposure) IEC 60068-2-27, half-sine pulse test parameters 20G, MIL-STD-810G METHOD 516.6 Table 516.6-II, sawtooth pulse test parameters Dust: IP30; EMC: CE, FCC, and ICES; Safety: IEC/EN/UL/CSA 63268-1
Dimensions	246 (W) x 107 (D) x 270 (H), 5.5 KG	211(W) x 240(D) x 86(H) mm, 5.2 Kg
Mounting	Wall Mount, Din Rail	Desktop, operational: wall mount
Operating System Options	Factory options for Ubuntu Desktop 16.04, Win7 Pro (via Win 10 Pro downgrade license), Win7 Pro for Embedded Systems (FES7), Win10 Pro, Win10 IoT Enterprise 2015 LTSC, Win Standard Embedded 7 (WES7P & WES7E).	Ubuntu Server 20.04 Win 10 IoT Enterprise LTSC 2019

Dell Edge Gateway 3200

Rich Storage

- M.2 SSD

Security

- TPM 2.0

Intel Elkhart Lake – Quad Core

- Intel Atom (x6425RE)
- Up to 32GB DDR4 memory

Optional Expansion

- CANbus
- PoE out
- 2 x Isolated Serial COM
- 2 x Isolated GbE
- DIO
- PoE in
- Sensors T, P, RH, GYRO

Front accessible I/O and Adaptive uFM module

- RS-232/422/485
- CANbus
- 2 x GbE
- 4 x USB 3
- 2 x DP++
- 2 x Serial COM
- 6-ch DI
- 6-ch DO

- -20°C to 60°C operating temperature
- Compact, Fan-less and Rugged Design
- WiFi-6E, Bluetooth 5.2 and Certified Dual Nano SIM 4G & 5G options
- OEM ready options



TARGET WORKLOADS



Manufacturing

Simplify and automate data collection at every stage of the production cycle



Telecom

Accelerate innovation and revenue growth with new services



Retail

Personalize customer experience with data insights



Smart Cities

Improve quality of life by increasing the city's efficiency

EDGE / TELCO

Technical Specifications – EGW3200

Features	Embedded PC 3000	Edge Gateway 3200
CPU	Intel Atom Processors E3800 Series	Intel Atom (x6425RE)
Memory	4G or 8G DDR3L	1 x DDR4 SO-DIMM socket, supporting up to 32GB DDR4 3200 MHz memory
Storage (Chassis options)	1 x HDD or 1 x SSD m.2 SSD (interposer). 500GB & 1TB HDD 32GB, 64GB & 128GB SSD	1 x M.2 SSD storage on M.2 Socket 3 64GB, 256GB, 512GB, 1TB M.2 M key 2242
Display	1 x VGA 1 x DP 1.1	2 x DP++
Ethernet	2 x Gigabit Ethernet: 2 x RJ-45	1 x 2.5 GbE, 1 x GbE (1 GHz)
Serial Ports	3 x COM Ports	2 x COM Ports (RS-232/422/485)
DI/O	N/A	6-ch DI and 6-ch DO
USB	1 x USB 3.0 4 x USB 2.0	4 x external USB ports 3.1 Gen 1
Audio	Mic-in, Line-in, Line-out	Line-out, mic-in
Mini PCIe		1 x full size 3050, used for WiFi by default
M.2	2 PCI/PCIe slots: riser card options: 2 x PCI, 1 x PCI + 1 x PCIe x 16 or 2 PCIe x8	Socket 1: for module with A/A+E key; Socket 2: for module with B/B+M key; Socket 3: for module with M key
Sensor Suite		accelerometer, humidity, pressure, temperature
Power Supply	Nominal input 24V DC (12-26V). Also accepts Dell AC adapter, 180W with locking plug	DC Input 9–36 VDC (±10% tolerance) Standard AC Input Optional: 120 W and 60 W (for PoE) external AC/DC adapter
Wireless	Wifi-4 Bluetooth LE	WiFi-6E Bluetooth 5.2
WWAN	3G or LTE	Dual NanoSIM (exterior): 4G & 5G certified GNSS (GPS)
Operating Temperature	0°C to 50°C	-20°C to 60°C , with airflow 0.6 m/s
Certs and Tests	ASTM-D4169-04, Random Operational Vibration, 0.52grms MIL-STD-810G, Method 514.6, Procedure 1, Cat 4 40G, MIL-STD-810G, Method 514.7, Procedure 1 (Shock)	MIL-STD-810G METHOD 514.6 category 4 - common carrier (US highway truck vibration exposure) IEC 60068-2-27, half-sine pulse test parameters 20G, MIL-STD-810G METHOD 516.6 Table 516.6-II, sawtooth pulse test parameters Dust: IP40, EMC: CE, FCC, and EN61000-6-4/-6-2, Safety: UL, CB by UL
Dimensions	237(W) x 60(D) x 161(H) mm, 2-3 kg	162 (W) x 108 (D) x 60 (H) mm, 1.7 Kg
Mounting	Wall, DIN-rail or VESA mounts	Wall mount, Optional DIN rail
Operating System Options	Microsoft Win7 Pro, Win7 Pro for Embedded Systems, Ubuntu Desktop 16.04. Later 2016: Windows 10 Pro, Windows 10 IoT Enterprise LTSC	Ubuntu Server 20.04 Windows 10 IoT Enterprise LTSC 2019

Accelerate insights...

No compromise AI Acceleration

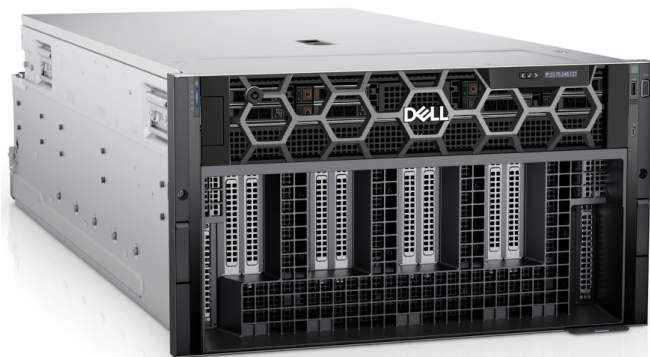


Workloads

AI - ML/DL Training

High-Performance Computing

Targeted workloads and verticals, including CRISP, Healthcare, CSP, Finance, HPC, Federal, Academia



XE9680: 6U/2S

Boost insights from your growing data sets with AI acceleration technology designed for optimal performance, fastest time-to-value and air-cooled operations.



Accelerate your outcomes with AI

Powerful AI training performance with 8 interconnected NVIDIA H100 GPUs and up to 350W CPUs, enabling faster business decisions



Air Cooled Design

6U chassis supports the highest wattage next gen technologies with Dell Smart Cooling and multi-vector cooling



Massive flexibility

Scale up capabilities with choice of NVIDIA H100 or A100 GPUs, up to 16 drives and 10 PCI Gen5 slots

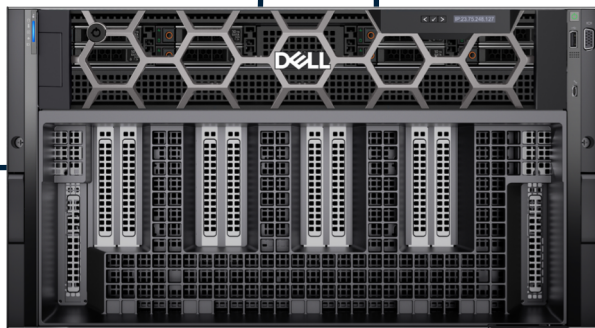
PowerEdge XE9680

2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor
- 6U air-cooled, up to 35C ambient
- 1200mm rack capable

Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- Up to 4800 MT/s (1DPC) or 4400 MT/s (2DPC)



I/O

- 10 x 16 PCIe Gen5 slots
- One OCP NIC 3.0
- 2 x 1GbE LOM

AI

Large Model Training

Support for up to 16 Drives

- Up to 8 x SAS/SATA/NVMe Gen4 or 16x E3.S
- Rear Hot-Plug BOSS N-1 (2 x M.2 MVNe) for boot (optional)
- SW RAID/PERC12 support

GPU Optimized

- NVIDIA 8 x H100 SXM5 700W 80GB GPUs
- -or-
- NVIDIA 8 x A100 SXM4 500W 80GB GPUs
- Full NVLINK interconnectivity

TARGET WORKLOADS

AI-ML/DL Training

Best-performing GPUs enable max performance for AI/ML-training workloads - especially for large model training

High-Performance Compute

High performance compute, higher CPU and GPU core density per rack enables HPC simulation modeling

Targeted Verticals

Healthcare, CSP & CRISP, Finance, HPC, Federal, Research/Universities

GPU OPTIMIZED

Technical Specifications – XE8545, XE8640, XE9680

Features	PowerEdge XE8545	PowerEdge XE8640	PowerEdge XE9680
CPU	Up to two 3 rd Generation AMD EPYC™ processors with up to 64 cores per processor Support for up to 2 x 280W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor, Support for up to 2 x 350W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors
Memory	16x or 32 x DDR4 DIMM Speed: Up to 3200 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 10x 2.5" Hot Plug SAS/SATA or up to 8x NVMe BOSS	Up to 8 E3.S Gen5 NVMe or SAS/NVMe 2.5" SSDs BOSS-N1 (2 x M.2 NVMe) for boot	Up to 16 E3.S Gen5 NVMe or 8 2.5" SAS/NVMe SSDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	S1.5, H745, H755	PERC12, SW RAID	PERC12, SW RAID
Network	Optional OCP NIC 3.0, Fixed 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM
PCIe slots	1 x PCIe Gen4 LP (x16) 1 x PCIe Gen4 FH (x16) 1 x PCIe Gen4 FH (x16) or 2 x PCIe Gen4 FH (x8)	4 x PCIe Gen5 Full Height (x16)	10 x PCIe Gen5 Full Height (x16)
GPU	4 x A100 GPUs with NVLink. Options: 40GB/400W or 80GB/500W	4 x H100 NVIDIA 700W SXM5 NVLINK GPUs	8 x H100 NVIDIA 700W SXM5 NVLINK GPUs 8 x A100 NVIDIA 500W SXM4 NVLINK GPUs
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0	iDRAC9 Express (base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct	iDRAC9 Express (base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct
High Availability	Hot Plug/RAID controlled drives, BOSS, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs
Power Supplies	2 + 2 2400W Redundant Hot Plug	4 x 2800W Titanium 208-240Vac PSUs with 3+1 Redundancy	6x 2800W Titanium 208-240Vac PSUs with 5+1 Redundancy
Thermals	Air Cooled Up to 35C	Air cooled via internal Liquid Assist Air Cooling up to 35C	Air Cooled up to 35C
Dimensions	H x W x D: 4U x 477mm x 810mm	H x W x D: 4U x 482mm x 866mm (1070mm Rack Compliant)	H x W x D: 6U x 482mm x 1001mm (1200mm Rack Compliant)
Form Factor	4U Rack Server	4U Rack Server	6U Rack Server

Accelerate innovation ...

Dense, smart acceleration



Workloads

AI & ML/DL Training
Modeling & Simulation

HPC & Super Computing

Targeted workloads and vertical,
including Healthcare, Life Sciences,
Academia

Unlock insights with purpose-built performance in a highly dense, smart cooled server for AI, removing traditional computational boundaries of real-time insights



XE9640: 2U/2S

- ✓ **Dense Acceleration**
Optimized 4-way interconnected Intel GPUs drive demanding ML/DL training and simulation modeling in 2U
- ✓ **Efficiently cooled**
Direct liquid cooled CPUs and GPUs maximizes performance, power utilization efficiency and lowers TCO
- ✓ **Flexible I/O**
Maximize operations with 4 PCIe Gen5 slots for 1:1 mapping with GPU for continuous utilization

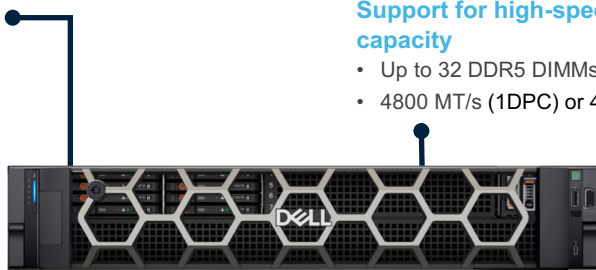
PowerEdge XE9640

Dual Socket

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor
- Direct Liquid cooled CPUs & GPUs
- 1200mm rack capable

Diverse GPU Offerings

Direct Liquid Cooled



Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- 4800 MT/s (1DPC) or 4400 MT/s (2DPC)

I/O

- Up to 4 x 16 PCIe Gen5 slots
- OCP 3.0 for network cards

Support for up to 8 Drives

- NVMe U.2 Gen4 or E3.S Gen5 drives
- Hot-Plug BOSS N-1 for boot (optional)

GPU Flexibility & Optimization

- 4x NVIDIA 700W SXM GPUs
-or-
- 4x Intel Data Center GPU Max Series 1550 600W OAM GPUs
- Quad connected NVLink or XeLink capability across GPUs

GPU OPTIMIZED

TARGET WORKLOADS

AI-ML/DL Training

Best performing GPUs enable max performance/\$ for AI/ML Training workload

High-Performance Compute

Higher CPU and GPU core density,
Liquid Cooled to

- **Lower TCO**
- **Maximize Rack Utilization**
- **Enable Green Data Centers**

Targeted Workloads and Verticals

Workloads: ML/DL Training & Simulation Modeling
Verticals: Finance, Healthcare, Higher-Ed, Fed, Retail, CSP & CRISP, Super Computing

Technical Specifications – XE8545, XE9640

Features	PowerEdge XE8545	PowerEdge XE9640
CPU	Up to two 3 rd Generation AMD EPYC™ processors with up to 64 cores per processor Support for up to 2 x 280W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors
Memory	16x or 32 x DDR4 DIMM Speed: Up to 3200 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s
Storage	Up to 10x 2.5" Hot Plug SAS/SATA or up to 8x NVMe BOSS	Up to 8 E3.S Gen5 NVMe or 4 2.5" NVMe Gen4 SSDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	S1.5, H745, H755	SW RAID
Network	Optional OCP NIC 3.0, Fixed 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM
PCIe slots	1 x PCIe Gen4 LP (x16) 1 x PCIe Gen4 FH (x16) 1 x PCIe Gen4 FH (x16) or 2 x PCIe Gen4 FH (x8)	2 x PCIe Gen5 FH (x16) 2 x PCIe Gen5 LP (x16)
GPU	4 x A100 GPUs with NVLink. Options: 40GB/400W or 80GB/500W	4 x H100 NVIDIA 700W SXM5 NVLink GPUs or 4 x Intel Data Center Max 1550 600W OAM XeLink GPUs
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0	16G iDRAC Express(base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct
High Availability	Hot Plug/RAID controlled drives, BOSS, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs
Power Supplies	2 + 2 2400W Redundant Hot Plug	Up to 4 x 2800W Titanium 208-240Vac PSUs with 2+0, 2+1 or 2+2 Redundancy
Thermals	Air Cooled up to 35C	Direct Liquid Cooled CPUs & GPUs. Air Cooled up to 35C for remaining components.
Dimensions	H x W x D: 4U x 477mm x 810mm	H x W x D: 2U x 482mm x 930mm
Form Factor	4U Rack Server 810mm (1070mm rack capable)	2U Rack Server (1200mm Rack Compliant. Requires 750mm wide for liquid manifolds)

Accelerate innovation ...

Purpose-built performance



Workloads

AI - ML/DL Training

High Performance Computing

Targeted applications and verticals such as Oil & Gas, Healthcare, CSP, Finance, HPC, Federal, Academia

Drive demanding AI, HPC and Data Analytics workloads and power users with optimized compute and accelerated throughput, to automate analysis into insights



XE8640: 4U/2S



Accelerate your outcomes with AI

Faster AI training performance with 4 interconnected NVIDIA H100 GPUs and up to 350W TDP CPUs



Air Cooled Design

4U chassis supports the highest wattage next gen technologies with Dell Multi vector cooling hybrid air/liquid approach



Scale up flexibility

Increase core capabilities with up to 4 PCI Gen5 slots, NVIDIA Multi-instance GPUs and GPU Direct Storage for fastest data transfers

PowerEdge XE8640

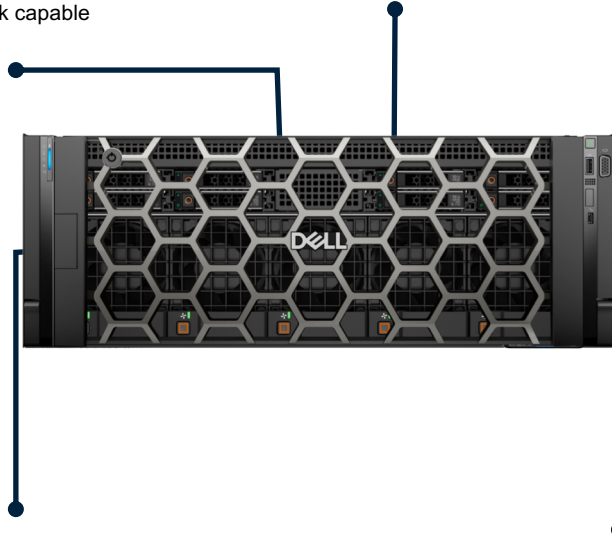
2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor
- 4U air-cooled (LAAC), up to 35C ambient
- Standard (1070mm) rack capable

Support for high-speed and memory capacity

- Up to 32 DDR5 DIMMs
- 4800 MT/s (1DPC) or 4400 MT/s (2DPC)

HPC & AI



Support for up to 8 Drives

- SAS SSD, or NVMe U.2 or E3.S drives
- Rear Hot-Plug BOSS N-1 (2 x M.2 MVNe) for boot (optional)
- SW RAID/PERC12 support

I/O

- Up to 4 x16 PCIe Gen5 slots
- OCP NIC 3.0
- 2 x 1GbE LOM

GPU Optimized

- Nvidia 4 x H100 SXM5 700W 80GB GPUs
- Full NVLINK interconnectivity

GPU OPTIMIZED

TARGET WORKLOADS

AI-ML/DL Training

Best-performing GPUs enable max performance for AI/ML-training workloads

High-Performance Compute

High performance compute, higher CPU and GPU core density per rack enables HPC simulation modeling

Targeted Verticals

Oil & Gas, Finance, Healthcare, HPC, Fed, Retail, CSP, Research/Universities

Technical Specifications – XE8545, XE8640, XE9680

Features	PowerEdge XE8545	PowerEdge XE8640	PowerEdge XE9680
CPU	Up to two 3 rd Generation AMD EPYC™ processors with up to 64 cores per processor Support for up to 2 x 280W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor, Support for up to 2 x 350W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Support for up to 2 x 350W processors
Memory	16 x or 32 x DDR4 DIMM Speed: Up to 3200 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s	Up to 32 x DDR5 RDIMMs DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Up to 10 x 2.5" Hot Plug SAS/SATA or up to 8x NVMe BOSS	Up to 8 E3.S Gen5 NVMe or SAS/NVMe 2.5" SSDs BOSS-N1 (2 x M.2 NVMe) for boot	Up to 16 E3.S Gen5 NVMe or 8 2.5" SAS/NVMe SSDs Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	S1.5, H745, H755	PERC12, SW RAID	PERC12, SW RAID
Network	Optional OCP NIC 3.0, Fixed 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM	Optional OCP NIC 3.0, Optional 2 x 1GbE LOM
PCIe slots	1 x PCIe Gen4 LP (x16) 1 x PCIe Gen4 FH (x16) 1 x PCIe Gen4 FH (x16) or 2 x PCIe Gen4 FH (x8)	4 x PCIe Gen5 Full Height (x16)	10 x PCIe Gen5 Full Height (x16)
GPU	4 x A100 GPUs with NVLink. Options: 40GB/400W or 80GB/500W	4 x H100 NVIDIA 700W SXM5 NVLINK GPUs	8 x H100 NVIDIA 700W SXM5 NVLINK GPUs 8 x A100 NVIDIA 500W SXM4 NVLINK GPUs
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct, Quick Sync 2.0	iDRAC9 Express (base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct	iDRAC9 Express (base), Enterprise, Datacenter Full Support; Open Manage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager) iDRAC Direct
High Availability	Hot Plug/RAID controlled drives, BOSS, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs
Power Supplies	2 + 2 2400W Redundant Hot Plug	4 x 2800W Titanium 208-240Vac PSUs with 3+1 Redundancy	6x 2800W Titanium 208-240Vac PSUs with 5+1 Redundancy
Thermals	Air Cooled Up to 35C	Air cooled via internal Liquid Assist Air Cooling up to 35C	Air Cooled up to 35C
Dimensions	H x W x D: 4U x 477mm x 810mm	H x W x D: 4U x 482mm x 866mm (1070mm Rack Compliant)	H x W x D: 6U x 482mm x 1001mm (1200mm Rack Compliant)
Form Factor	4U Rack Server	4U Rack Server	6U Rack Server

Accelerate innovation ...

More capable & agile AI compute



Workloads

AI/ML/DL Training medium to large data sets

HPC, VDI, performance graphics

Digital Twins, Render farms, virtualization



R760xa: 2U/2S

Maximize your results from AI to modeling & simulation with scale-as-you-grow compute, supporting maximum flexibility in small density.



Deploy with ease

Drive traditional and emerging workloads with a powerful 2U server, the latest 4th Gen Intel Xeon processors and air-cooled design



Flexible acceleration

Boost AI outcomes across a wide range of workloads and scale out as business grows with expandable support from up to 4x 350W GPUs, or 12x single-wide GPUs.



Deliver outcomes

Faster time to results from application performance with support from up to 4x 350W GPUs, or 12x single-wide GPUs.

Dell EMC PowerEdge R760xa

2 Socket Capable

- Two 4th Gen Intel® Xeon® Scalable processors through highest TDP
- 2U Mainstream-designed
- Standard (1070mm) rack capable

Support for high-speed and memory capacity

- 32 DDR5 DIMMs
- 4800 MT/s

Mainstream PowerEdge Design

Supports wide range of accelerated workloads

Flexible Infrastructure to run mixed workloads and scale as needed



I/O

- Up to 4 x16 350W PCIe Gen5 slots
- OCP 3.0 for network cards

GPU Optimized

- Up to 4x DW or 10x SW PCIe Gen5 GPUs powered by NVIDIA, Intel and AMD
- NVLINK Bridging support enables scaling of memory and performance to enhance GPU focused applications
- Multi-Instance GPU (MIG) enabled for multi-tenancy
- Supports entire Dell PowerEdge PCIe portfolio

Support for up to 8 Drives

- SAS/SATA/NVMe U.2 or E.3 SSD drives
- Hot-Plug BOSS for boot (optional)
- PERC12 support (SAS4/NVMe)

Air-Cooled to 35C

- Optional DLC for 20% more heat capture

TARGET WORKLOADS



AI-ML/DL Training and Inference

Flexible accelerator configurations enable optimal perf/\$ AI-ML/DL workloads together with inferencing



High-Performance Compute

Higher CPU and GPU core density enable HPC simulation modeling



Render Farms and Virtualization

Higher GPU utilization using multi-tenancy to serve multiple users without compromising on density

Technical Specifications – R750xa, R760xa

Features	PowerEdge R750xa	PowerEdge R760xa
CPU	Up to two 3 rd Generation Intel® Xeon® Scalable processors, up to 40 cores per processor Support for up to 2 x 270W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors, up to 56 cores per processor Support for up to 2 x 350W processors
Memory	Up to 32 x DDR4 (up to 16 Barlow Pass) 3200 MT/s	Up to 32 x DDR5 RDIMMs @ 4800 MT/s
Storage (Chassis Options)	Up to 8x 2.5" SAS/SATA SSD -or- NVME BOSS	Up to 8x 2.5" SAS/SATA/NVMe -or- 6x E3.S Gen5 NVMe SSD Rear Hot-Plug BOSS-N1 (2 x M.2 NVMe) for boot
Storage Controller	PERC 10.5 for Mid-tier PERC 11 for High-end (2x performance vs. PERC 10.5)	PERC11 + PERC12 (SAS4/NVMe)
Network	2 x1GbE LOM+1 x8 Gen4 OCP 3.0	Optional OCP NIC 3.0 Optional 2x 1GbE LOM
PCIe slots	2 x16 Gen4 LP PCIe + 2 x8 Gen4 FH PCIe (cannot combine with 6x 2.5" NVMe)	4 x16 Gen5 FHHL slots
GPU	Supports up to 4x Double-Wide 300W GPUs -or- 6x Single-Wide 75W GPUs Optional NVLink Bridging	Up to 4x Double-Wide 350W GPUs -or- up to 12x Single-Wide 75W GPUs Optional NVLink Bridging
Integrated Ports	Front: 1x USB 2.0, 1x iDRAC Direct micro-USB + front VGA Rear: 1x USB 3.0 + 1x USB 2.0, Dedicated iDRAC port, VGA	Front: 1x USB 2.0, 1x iDRAC Direct micro-USB + front VGA Rear: 1x USB 3.0 + 1x USB 2.0, Dedicated iDRAC port, VGA
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct, Quick Sync 2.0
High Availability	Hot Plug/RAID controlled drives, BOSS, PSUs	Hot Plug/RAID controlled drives, BOSS-N1, PSUs
Power Supplies	1400W, 2400W	Dual PSUs 2400W -or- 2800W
Thermals	High performance fans; Air-Cooled to 35C with optional CPU liquid cooling support	High performance fans; Air-Cooled to 35C with optional CPU liquid cooling support
Dimensions	H x W x D: 2U x 482mm x 895mm (1070mm rack compliant)	H x W x D: 2U x 482mm x 875mm (1070mm rack compliant)
Form Factor	2U Rack Server	2U Rack Server

Reimagine IT Possibilities...

What's new with our R760xd2?



Workloads

File and object storage
Video capturing & surveillance

Video streaming

More capable & agile storage solution



Meet your growing unstructured data needs with object storage technology that is easily configurable, and serviceable.



Save more data

With a 7% increase in the number of 3.5 inch drives.



Increase flexibility

Ability to natively tier 3.5 inch spinning drives with solid state NVMe drives.



Save on service

Cut your serviceability cost using our new external rail system.

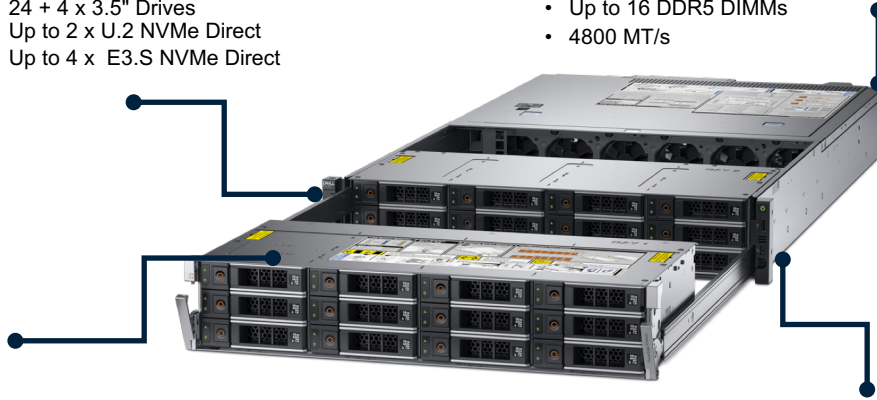
PowerEdge R760xd2

Support for up to 28 Drives

- 24 + 4 x 3.5" Drives
- Up to 2 x U.2 NVMe Direct
- Up to 4 x E3.S NVMe Direct

Support for high-speed and memory capacity

- Up to 16 DDR5 DIMMs
- 4800 MT/s



2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor
- Support for NVIDIA GPUs

Flexible I/O

- Up to 4 x PCIe Gen4 slots
- OCP 3.0 for network cards
- Rear Hot-Plug BOSS N-1 (2 x M.2 NVMe) for boot (optional)

- Support for latest generation of density optimized 3.5" storage drives
- Ability to provide HW options for native in box tiering
- Industry-leading manageability and security

TARGET WORKLOADS



Object

Ideal for massively scalable storage solutions optimized for cost/GB



File

Balanced core count, memory and networking to support open market and vendor optimized file storage



Video surveillance and analytics

For datacenters that require ample storage for video surveillance applications with the option for in box analytics

STORAGE OPTIMIZED

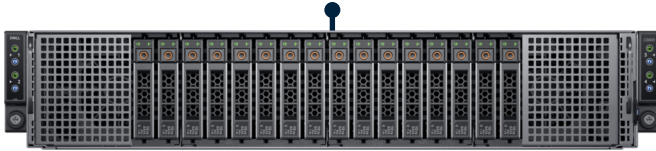
Technical Specifications – R740xd2, R760xd2

Features	PowerEdge R740xd2	PowerEdge R760xd2
CPU	Up to two 2 nd Generation Intel® Core processors with up to 16 cores per processor Support for up to 2 x 140W processors	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Support for up to 2 x 185W processors
Memory	Up to 16 x DDR4 RDIMMs NVDIMM: No DIMM Speed: Up to 3200 MT/s	Up to 16 x DDR5 RDIMMs NVDIMM: No DIMM Speed: Up to 4800 MT/s
Storage (Chassis options)	Front: Up to 24 x 3.5" SAS/SATA Rear: Up to 2 x 3.5" SAS/SATA 3.5" or SSD	Front: Up to 24 x 3.5" SAS/SATA HDDs Rear: Up to 4 x 3.5" Universal or Up to 2 x U.2 NVMe Direct or Up to 4 x EDSFF E3.S NVMe Direct
PCIe Storage	None	Up to 2 x U.2 NVMe Direct Up to 4 x E3.S NVMe Direct
Storage Controller	PERC H740P or HBA330	PERC 11 (H755) or PERC 12 (H965), HBA355i, H465e, H965e, HBA355e or HBA 355
Boot Controller	BOSS (internal)	Rear Hot Plug BOSS-N1 (2 x M.2 NVMe) for boot
Network	2 x 1GbE LOM + 1 x OCP 3.0	2 x 1GbE LOM + 1 x OCP Mezz 3.0 x8 Gen 4
PCIe slots	Up to 2 x PCIe Slots Gen3	Up to 4 x PCIe Slots Gen4 (mix of LP, HL, FL, DW)
GPU	None	Support for NVIDIA GPUs Up to 2 x 16 FH 70W PCIe 4.0 (A2) Up to 1 x 16 DWFL 180W GPU PCIe 4.0 (A30)
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA Optional Internal USB	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB + front VGA Rear: 1 x USB 3.0 + 1 x USB 2.0, Dedicated iDRAC port, VGA Optional Internal USB
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager). iDRAC Direct
High Availability	Hot Plug/RAID controlled drives, PSU, iSDSM, BOSS (2 x M.2)	Hot Plug/RAID controlled drives, PSU, 3-Tiered Hot Plug Fans, NVME BOSS-N1 (2 x M.2)
Power Supplies	750W, 1100W	Dual 15G 60mm PSUs 48Vdc/1100W, 700W, 1400W, 1800W
Dimensions	H x W x D: 2U x 434mm x 813mm	H x W x D: 2U x 434mm x 837mm
Form Factor	2U Rack Server	2U Rack Server

PowerEdge C6620

Support for 16 x NVMe Gen4 Drives

- 4 x NVMe Gen4 drives/compute node



Up to 4 Nodes

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor
- Memory speed up to 4800 MT/s

Flexible I/O

- Up to 2 x PCIe Gen5 slots
- 1 x 16 PCIe Gen5 OCP 3.0 for network cards
- SNAP I/O Support

- New PowerEdge C6600 chassis with improved power, thermal capabilities
- Direct Liquid Cooling (DLC) Support
- Industry-leading manageability and security

TARGET WORKLOADS



High-Performance Computing

High compute performance, higher core/node density per rack enables HPC, Research, Rendering, Vectorized and Advanced Vector Extensions (AVX).



Financial analysis / High Frequency Trading

Medium Duty traditional database & scale out database with low-medium local storage



Hyper-Performance Compute

HPC requiring 1DPC design for highest memory performance & scale out clusters.

MODULAR

Technical Specifications – C6520, C6620

Features	PowerEdge C6520	PowerEdge C6620
Chassis	C6400 Chassis	C6600 Chassis
CPU	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 40 cores per processor Air and Direct Liquid Cooling support (configuration restrictions apply due to thermal/power limits)	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor Air and Direct Liquid Cooling support (configuration restrictions apply due to thermal/power limits)
Memory	DDR4: 8 channels/CPU; Up to 16 x RDIMMs and LRDIMMs DIMM Speed: Up to 3200 MT/s Intel Optane Persistent Memory 200 series: No	Up to 16 x DDR5 RDIMMs; 8 channels/CPU DIMM Speed: Up to 4800 MT/s
Storage	Backplanes: Up to 24 x 2.5" Options: 1) Direct: SAS/SATA; 2) SAS/SATA with 2 NVMe drives Up to 24 x 2.5" all NVMe Up to 12 x 3.5" Diskless configuration Internal: uSD Card, M.2 SATA BOSS 1.0	Backplanes: Up to 16 x 2.5" SAS/SATA Up to 16 x 2.5" all NVMe Diskless configuration Internal: BOSS-N1 (2 x M.2 NVMe) for boot, HW-RAID and SED
Storage Controller	HW RAID: PERC 10.5 H345/H350 , H745/H750, HBA 345/355i Chipset SATA/SW RAID: Yes, S150	HW RAID: PERC 11.5 - H355, H755, HBA355i; PERC12 – H965i Chipset SATA/SW RAID: Yes, S160
Network	Single port 1GbE LOM	Single port 1GbE LOM
PCIe slots	2 x PCIe Gen4 HH/HL slots, x16 (network, storage, AIC), 1 x16 Gen4 OCP 3.0 slot	2 x 16 PCIe Gen5 HH/HL slots, x16 (network, storage, AIC), 1 x 16 PCIe Gen5 OCP 3.0 slot
Integrated Ports	Rear ports: 1 x USB 3.0 Micro USB port for iDRAC direct Mini Display Port for video	Rear: 1 x USB 3.0 Micro USB port for iDRAC direct Mini Display Port for video
System Management	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager), iDRAC Direct	iDRAC9 Enterprise, Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager), iDRAC Direct
Accelerators	Up to one GPU/FPGA/PAC (up to 75W)	Up to one GPU/FPGA/PAC (up to 75W)
Power Supplies	1600W, 2000W AC DC (Mix Mode), 2400W, 2600W	2400W, 2800W, and 3200W(277Vac available in NA region only)
Dimensions	H x W x D: 86.80mm x 448.00mm x 790.00mm	H x W x D: 86.80mm x 448.00mm x 790.00mm
Form Factor	2U rack mounted multi-node server	2U rack mounted multi-node server

C6600 Chassis Options

C6400



C6600



No Backplane Chassis

- No front drives; Internal Boot using M.2 Boot Drive
- Improved air flow and thermal capability
- **HPC, HFT, SaaS/aaS, Hadoop compute node w/ external HDFS storage**

16x 2.5" All NVMe Backplane Chassis

- Optimized for applications requiring high-speed storage
- Up to 4 NVMe (Gen4) drives/compute sled; internal M.2 boot drive
- **vSAN, SDS, HPDA, HCI**

16x 2.5" SAS/SATA Backplane Chassis

- Optimized for high performance compute and storage
- Up to 4 SAS/SATA drives/compute sled; internal M.2 boot drive
- **HPC, HPDA, SaaS/aaS, Financial modelling, HCI, vSAN**

PowerEdge MX760c

Flexible I/O

- 3 x High throughput, low latency Fab A,B and C



Up to 8 x EDSFF E3.S NVMe Gen5 or 6 x 2.5" SAS/SATA or NVMe Gen4

- Internal BOSS-N1 (M.2 NVMe) for boot /HW - RAID and SED)
- PERC12 - H965i NVMe Raid

Support for higher-speed and dense memory capacity

- Optimized for 2 DIMMs/channel
- 32 DDR5 DIMMs
- 4800 MT/s

2 Socket Capable

- Up to two 4th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor

- Designed for PowerEdge MX7000 Modular chassis
- Integrated Intel® Built-In AI Acceleration, Next Gen QAT
- Industry-leading manageability and security

TARGET WORKLOADS



General Purpose IT, Virtualization, Containerization, Business Applications

Scalable processor core count, higher performance memory configurations, sufficient storage capacity and networking capabilities



Software-Defined Storage and Software-Defined Networking

Flexible and richer storage configs
High speed networking support
Redundant IO



Database, Big Data Analytics

Compute and memory rich configurations (Structured and Unstructured DB, In-Memory DB, Big Data analytics)

MODULAR

Technical Specifications – MX750c, MX760c

Features	PowerEdge MX750c	PowerEdge MX760c
Chassis	MX7000	MX7000
CPU	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 40 cores per processor 3 x UPI @ 11.2 GT/s	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 56 cores per processor 4 x UPI @ 24 GT/s
Memory	DDR4: 8 channels/CPU; Up to 32 x RDIMMs and LRDIMMs DIMM Speed: Up to 3200 MT/s Intel Optane Persistent Memory 200 series	Up to 32 x DDR5 RDIMMs; 8 channels/CPU DIMM Speed: Up to 4800 MT/s
Storage	6 x 2.5" SAS, SATA, NVMe (Gen4) Internal: uSD Card, M.2 SATA BOSS 1.5	8 x E3.S NVMe (Gen5 x4) 6 x 2.5" SAS/SATA SSDs or NVMe (Gen4) SSDs Internal: Internal BOSS-N1 (2 x M.2 NVMe) for boot, HW-RAID and SED
PCIe Storage	Up to 6 NVMe 2.5" drives (Direct)	Up to 8 EDSFF E3.S NVMe (Direct)
Storage Backplane	x 6 Universal Backplane x 6 SAS/SATA Backplane x 4 Universal Backplane	8 x E3.S NVMe Backplane (Gen5 x4) x 6 Universal Backplane x 6 SAS/SATA Backplane x 4 Universal Backplane
Storage Controller	S150 Software RAID PERC HBA330 H755 Performance RAID, NVMe RAID H745P Performance RAID, internal and external drive connect HBA350i MX mini-mezz, HBA, external drive connect	S150 Software RAID H755 Performance RAID, NVMe RAID H965i Performance RAID, SAS/SATA or NVMe RAID HBA355i MX mini-mezz, HBA, external drive connect
IO slots and Network	Dual Port and Quad Port Mezz 25G, Dual Port FC32G, PCIe Gen4 enabled Up to 2 pair redundant general-purpose switch or pass-through module bays (Fabrics A and B); redundant pair of storage specific switch bays (Fabric C)	Dual Port and Quad Port Mezz 25G, Dual Port FC32G, PCIe Gen4 enabled Up to 2 pair redundant general-purpose switch or pass-through module bays (Fabrics A and B); redundant pair of storage specific switch bays (Fabric C). Fab B: PCIe Gen5 enabled and Fab C: Gen 4 connection to CPU1
System Management	iDRAC9 with Lifecycle Controller, OME-M1.3, OME 3.6	iDRAC9 with Lifecycle Controller, OpenManage Enterprise-Modular 1.3, OME v3.10 & v3.11 Datacenter license options; OpenManage Enterprise and Plugins (Power Manager, SupportAssist, and Update Manager)
High Availability	Hot Plug/RAID controlled Drives, BOSS-S2 RAID1 (2 x M.2)	Hot Plug/RAID controlled drives, NVMe BOSS-N1 RAID 0/1 (2 x M.2)
Power Supplies	3000W AC	3000W AC
Dimensions	257 x 51 x 631.72 mm	257 x 51 x 631.72 mm
Form Factor	7U Chassis, single-width compute sled	7U Chassis, single-width compute sled

Reimagine IT Possibilities...

Open platform, cloud scale servers* designed for Cloud Service Providers

Workloads

Cloud/Virtualization

Software-Defined Storage Node

Scale-out Database



HS5610 : 1U/2S

1U with Cold Aisle config option



HS5620: 2U/2S

Flexibility with more storage and PCIe slots

Delivers leading-edge technology tailored for large-scale, heterogeneous SaaS, IaaS, and PaaS datacenters



Designed for 70% of CSP workloads

Broad selection of Intel medium core count CPUs, right-sized memory, and a cold aisle serviceable configuration with front I/O



Powering Choice with Open Ecosystem Options

Ideal for management across multi-vendor systems, Open Server Manager is an open-source management option built from OpenBMC™



Tailored to Fit

Configurations that easily scale to support cloud service providers with select components and validated workloads to minimize extra costs and overhead

*Exclusive through the **Hyperscale Next program** for select customers.

PowerEdge HS5620 Key Features

Optimized for Cloud Service Providers

- Powered by up to two next-generation Xeon Scalable processors, code-named "Sapphire Rapids"
- Single processor configurations available
- Up to 16 x DDR5 RDIMMs (2TB max)
- Up to 4800 MT/s

System Management

- iDRAC or OpenBMC+ **NEW**



Flexible Storage

- 8x 2.5" NVMe or SAS/SATA
- 8x 3.5" SAS/SATA
- 12x 3.5" SAS/SATA + 2x 2.5" SAS/SATA or NVMe (optional)
- 16x 2.5" SAS/SATA + 8x 2.5" NVMe
- SW RAID, BOSS-N1, PERC11

I/O

- Up to 7 I/O slots:
 - 4x PCIe Gen4 slots
 - 2x PCIe Gen5 slots*
 - 1x OCP 3.0 for network cards
- Channel Firmware devices (NIC & NVMe)

- MCC TTM based on Intel embargo
- Early engineering samples and post-RTS efforts to assist
- CET Engineering lab resources
- CSP Services and Rack Integration

TARGET WORKLOADS



Virtualization

A perfect choice for medium businesses exploring the advantages of software virtualization



Medium VM density or VDI

Consider medium VM as an adaptable option to right size virtual instances or for VDI instances where accelerator support is not required



Software-Defined Storage Node

Up to 16 drives for software defined storage deployments (Media/Hadoop/grid)

*Gen5 PCIe: upsell

DELL Technologies

Technical Specifications – R750xs, HS5620

Features	R750xs	HS5620
CPU	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Up to two 220W TDP	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Up to two 250W TDP with HW config restriction
Memory	Up to 16 x DDR4 3200MT/s RDIMMs (1TB max) 8 channels, 1 DIMM/channel Optane Memory: No NVDIMM: No	Up to 16 x DDR5 4800 MT/s RDIMMs (2TB max) 8 channels, 1 DIMM/channel Optane Memory: No NVDIMM: No
Storage (Chassis options)	Up to 12 x 3.5" SAS/SATA + optional 2 x 2.5" SAS/SATA/NVMe (rear) Up to 8x 3.5" ChipsetSATA Up to 8x 2.5" NVMe Raid Up to 16x 2.5" SAS/SATA + optional 8x 2.5" NVMe (rear) Internal: IDSDM or USB, rear BOSS-S2 (2 x M.2) for boot	Up to 8x 2.5" NVMe/NVMe RAID Up to 8x 3.5" SAS/SATA/ChipsetSATA Up to 12x 3.5" SAS/SATA + optional 2x 2.5" SAS/SATA or NVMe (Rear) Up to 16x 2.5" SAS/SATA + 8x 2.5" NVMe Internal: Internal BOSS-N1 (2 x M.2 NVMe) for boot and USB (optional) Support for Channel Firmware NVMe SSD
Storage Controller	HW RAID: PERC 10.5 & 11 (no dual PERC option) PERC 10.5: H345, H745 PERC 11: HBA355, H755, H755N Chipset SATA/SW RAID: Yes	HW RAID PERC11 (no dual PERC option) PERC 11: HBA355i, H355, H755, H755N, HBA355e Chipset SATA/SW RAID: Yes
Network	2 x 1GbE + 1 x OCP 3.0 (x16)	Rear: 2 x 1GbE + 1 x OCP 3.0 (x8) Support for Channel Firmware OCP and PCIe NIC
I/O	Up to 5 x PCIe Gen4 (5 x16) Up to 1 x PCIe Gen3 (1 x8) with SNAPI support	Up to 7 I/O: 1 x OCP 3.0 (x) and up to 4 x PCIe Gen4 (x16/x16/x16/x8) + slots 2 x PCIe Gen5 (x16/x16) No SNAPI support
GPU	None	Up to 2 x Nvidia A2
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB, 1 x VGA Rear: 1 x USB 2.0, 1 x USB 3.0, 1 x Serial (option), 2 x network, 1 x iDRAC network, 1 x VGA	Front: 1 x USB2.0, 1 x iDRAC Direct micro-USB, 1 x VGA, Rear: 1 x USB 2.0, 1 x USB 3.0, 1 x Serial (option), 2 x network, 1 x iDRAC network, 1 x VGA
System Management	iDRAC9 Express, Enterprise, Datacenter and OME	iDRAC9 Express, Enterprise, Datacenter and OME Open Server Manager (OpenBMC)
High Availability	Hot plug hard drives, PSU, fans, and BOSS	Hot Plug/RAID controlled drives, PSU, fans, and BOSS.
Power Supplies	600W, 800W, 1100W, -48Vdc/1100W,1400W	600W, 700W, 800W, 1100W, 1400W, 1800W
Dimensions	H x W x D: 2U x 434mm x 721mm	H x W x D: 2U x 434mm x 721mm
Form Factor	2U Rack Server	2U Rack Server

PowerEdge HS5610 Key Features

Cold Aisle Serviceability **NEW**

- Easily serviceable from the cold aisle for efficient DC management (2x OCP + 6x 2.5")

Optimized for Cloud Service Providers

- Powered by up to two next-generation Xeon Scalable processors, code-named "Sapphire Rapids"
- Single processor configurations available
- Up to 16 x DDR5 RDIMMs (2TB max)
- Up to 4800 MT/s



Flexible Storage

- 4x 3.5" SAS/SATA
- 10x 2.5" SAS/SATA or NVMe
- 8x 2.5" SAS/SATA or NVMe
- 6x 2.5" NVMe
- Optional 2x 2.5" Rear SAS/SATA or NVMe
- SW RAID, BOSS-N1, PERC11

I/O

- Up to 3 I/O slots:
 - 2x PCIe Gen4 / Gen5 slots*
 - 1x OCP 3.0 for network cards

- Channel Firmware devices (NIC & NVMe SSDs)

System Management

- iDRAC or OpenBMC+ **NEW**

- MCC TTM based on Intel embargo
- Early engineering samples and post-RTS efforts to assist
- CET Engineering lab resources
- CSP Services and Rack Integration

TARGET WORKLOADS



Virtualization / Cloud

Medium density virtualization and Cloud-Native requiring low-medium local storage



Scale-Out Database

Medium Duty traditional database & scale out database with low-medium local storage



Software-Defined Storage Node

Up to 4 large capacity drives for software defined storage deployments (Media/Hadoop/grid)

*Gen5 PCIe: upsell

DELLTechnologies

Technical Specifications – R650xs, HS5610

Features	PowerEdge R650xs	PowerEdge HS5610
CPU	Up to two 3 rd Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Up to two 220W TDP	Up to two 4 th Generation Intel® Xeon® Scalable processors with up to 32 cores per processor Up to two 250W TDP with HW config restriction
Memory	Up to 16 x DDR4 3200 MT/s RDIMMs (1TB max) 8 channels, 1 DIMM/channel Optane Memory: No NVDIMM: No	Up to 16 x DDR5 4800 MT/s RDIMMs (2TB max) 8 channels, 1 DIMM/channel Optane Memory: No NVDIMM: No
Storage (Chassis options)	Up to 4 x 3.5" SAS/SATA/Chipset SATA + optional 2 x 2.5" SAS/SATA/NVMe (rear) Up to 10x 2.5" SAS/SATA/NVMe + optional 2 x 2.5" NVMe (rear) Up to 8x 2.5" NVMe RAID HW NVMe RAID (8 x 2.5" with PERC H755N) Internal: IDSD or USB, BOSS-S1 (2 x M.2) for boot	Up to 4x 3.5" SAS/SATA/ChipSATA HDD + optional 2x 2.5" SAS/SATA/NVMe SSD (Rear) Up to 8x 2.5" SAS/SATA/ChipSATA or NVMe/NVMe RAID + optional 2x 2.5" ChipsetSATA/NVMe (Rear) Up to 10x 2.5" SAS/SATA or NVMe + optional 2x 2.5" NVMe (Rear) Cold Aisle (CA): Up to 6x 2.5" NVMe (Gen 4) SSD Internal: Internal BOSS-N1 (2 x M.2) non-hot swap and USB (optional) CA: Front plug monolithic BOSS-N1 (2 x M.2), hot swap Support for Channel Firmware NVMe SSD
Storage Controller	HW RAID: PERC 10.5 & 11 (no dual PERC option) PERC 10.5: H345, H745 PERC 11: HBA355, H755, H755N Chipset SATA/SW RAID: Yes	HW RAID PERC11 (no dual PERC option) PERC 11: HBA355i, H355, H755, H755N Chipset SATA/SW RAID: Yes
Network	2 x 1GbE + 1 x OCP 3.0 (x16)	Rear: 2 x 1GbE + 1 x OCP 3.0 (x8) Cold-Aisle: 2 x OCP 3.0 (FLOP) Support for Channel Firmware OCP and PCIe NIC
PCIe slots	Up to 3 x PCIe Gen4 (x16/x8/x8) with SNAPI capability	Up to 3 x I/O: 1 OCP3.0(x8) and 2 PCIe Gen4 or Gen5 (x16/x16), No SNAPI support
GPU	None	None
Integrated Ports	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB, 1 x VGA Rear: 1 x USB 2.0, 1 x USB 3.0, 1 x Serial (option), 2 x network, 1 x iDRAC network, 1 x VGA	Front: 1 x USB 2.0, 1 x iDRAC Direct micro-USB, 1 x VGA, 1 x iDRAC network (CA-only), 1 x Serial (CA-only) Rear: 1 x USB 2.0, 1 x USB 3.0, 1 x Serial (option), 2 x network, 1 x iDRAC network, 1 x VGA
System Management	iDRAC9 Express, Enterprise, Datacenter, and OME	iDRAC9 Express, Enterprise, Datacenter, and OME Open Server Manager (OpenBMC)
High Availability	Hot plug hard drives, PSU, fans, and BOSS	Hot Plug/RAID controlled drives, PSU, and BOSS. Cold plug fans with optional hot-plug
Power Supplies	600W, 800W, 1100W, -48Vdc/1100W,1400W	600W, 700W , 800W, 1100W, -48Vdc/ 1100W, 1400W, 1800W
Dimensions	H x W x D: 1U x 434mm x 698mm (2.5" drives) or 749mm (3.5" drives)	H x W x D: 1U x 434mm x 698mm (2.5" drives) or 749mm (3.5" drives)
Form Factor	1U Rack Server	1U Rack Server